

Golden List of Reviewers for 2022

First Name	Last Name	Affiliation	Country
Sheikh	Aamir Ahsan	National Institute of Technology Srinagar	India
Yaser	Abdi	University of Tehran	Iran
Reza	Abdolvand	University of Central Florida	United States
Shela	Aboud	Synopsys Inc.	United States
Gina	Adam	The George Washington University	United States
Sheel	Aditya	Nanyang Technological University	Singapore
Harshit	Agarwal	Indian Institute of Technology Jodhpur	India
Ashish	Agrawal	Intel Corporation	United States
Tarun	Agrawal	ETH Zurich	Switzerland
Martina	Ahlberg	University of Gothenburg	Sweden
Abuduwayiti	Aierken	Yunnan Normal University	China
Deji	Akinwande	University of Texas at Austin	United States
Akin	Akturk	CoolCAD Electronics	United States
Md. Nur Kutubul	Alam	Katholieke Universiteit Leuven Faculteit Wetenschappen	Belgium
Monzurul	Alam	North Carolina Agricultural and Technical State University	United States
Muhammad A.	Alam	Purdue University	United States
Shamiul	Alam	The University of Tennessee Knoxville	United States
Manuel	Aldegunde	Synopsys Inc.	United Kingdom
Abdullah	Alharbi	King Abdulaziz City for Science and Technology	Saudi Arabia
Muhammad	Ali	Apple Inc.	United States
Asaad	Al-Mashaal	University of Edinburgh School of Engineering	United Kingdom
Mehadi	Aman	Sharp Corporation Tenri	Japan
Stefano	Ambrogio	IBM	United States
Elia	Ambrosi	Taiwan Semiconductor Manufacturing Company Ltd	Taiwan
Salvatore	Amoroso	Synopsys Inc.	United Kingdom
Chenxiang	An	National University of Defense Technology	China
Takashi	Ando	IBM	United States
Frédéric	André	Thales Electron Devices	France
Kah Wee	Ang	National University of Singapore	Singapore
Md. Hasan	Ansari	King Abdullah University of Science and Technology	Saudi Arabia
Marina	Antoniou	University of Warwick	United Kingdom
Dmytro	Apalkov	Samsung Electronics	United States
Hiroaki	Arimura	IMEC	Belgium
Carter	Armstrong	L-3 Communications Electron Devices Division	United States
Plamen	Asenov	Synopsys Inc.	United Kingdom
Joel	Asubar	University of Fukui	Japan
Jayasimha	Atulasimha	Virginia Commonwealth University	United States
Charles	Augustine	Intel Corporation	United States
Brian	Aull	Massachusetts Institute of Technology	United States
Carmine	Autieri	Polish Academy of Sciences	Poland
Ahmedullah	Aziz	University of Tennessee Knoxville	United States
Samuel	Bader	Cornell University	United States
Ghadeer	Badran	University of Huddersfield	United Kingdom

First Name	Last Name	Affiliation	Country
Byung Seong	Bae	Hoseo University	South Korea
Jong-Ho	Bae	Kookmin University	South Korea
Jong-Uk	Bae	LG Display	South Korea
Chang-Ki	Baek	POSTECH	South Korea
Rock-Hyun	Baek	POSTECH MSE	South Korea
Seung-Heon	Baek	Korea Institute of Science and Technology	South Korea
Maria Teresa	Baeza-Romero	University of Castilla-La Mancha	Spain
Eldad	Bahat Treidel	Ferdinand-Braun-Institut für Höchstfrequenztechnik	Germany
Pydi Ganga M.	Bahubalindrani	Indian Institute of Science Education and Research Bhopal	India
Ningfeng	Bai	Southeast University	China
Benoit	Bakeroot	IMEC	Belgium
Mietek	Bakowski	RISE	Sweden
Francis	Balestra	IMEP-LAHC	France
Luigi	Balestra	University of Bologna	Italy
B. Jayant	Baliga	North Carolina State University	United States
Writam	Banerjee	Pohang University of Science and Technology	South Korea
Wenzhong	Bao	Fudan University	China
Xinyu	Bao	TSMC Ltd	Taiwan
Hugh	Barnaby	Arizona State University	United States
Pedro	Barquinha	Universidade Nova de Lisboa FCT	Portugal
Michael	Basler	Fraunhofer Institute for Applied Solid State Physics IAF	Germany
Thomas	Basler	Technische Universität Chemnitz	Germany
Rupa	Basu	Lancaster University	United Kingdom
Joan	Bausells	Centro Nacional de Microelectronica	Spain
Mehdi	Bazizi	Applied Materials Inc.	United States
Arnout	Beckers	IMEC	Belgium
Thomas	Bedecarrats	CEA-Leti	France
Federico	Bella	Politecnico di Torino	Italy
Dan	Berco	Nanyang Technological University	Singapore
Radu	Berdan	Kioxia Corporation	Japan
Juan Paolo	Bermundo	Nara Institute of Science and Technology	Japan
Sven	Beyer	GlobalFoundries	Germany
Ratnajit	Bhattacharjee	Indian Institute of Technology Guwahati	India
Dhritiman	Bhattacharya	Virginia Commonwealth University	United States
Arkka	Bhattacharyya	University of Utah	United States
Krishna	Bhuwalka	IMEC	Belgium
Davide	Bisi	Transphorm Inc.	United States
Jasper	Bizindavyi	IMEC	Belgium
Monica	Blank	Communications and Power Industries	United States
Simon	Bleiker	KTH Royal Institute of Technology	Sweden
Boni	Boksteen	Hitachi ABB Power Grids	Switzerland
William	Borders	National Institute of Standards and Technology	United States
Matteo	Borga	IMEC	Belgium
Buddha Deka	Boruah	University of Cambridge	United Kingdom
Arijit	Bose	Nagoya Institute of Technology	Japan
Gianluca	Boselli	Texas Instruments	United States
Panagiotis	Bousoulas	National Technical University of Athens	Greece
Chris	Bowen	University of Bath	United Kingdom
Rita	Branquinho	Universidade Nova de Lisboa	Portugal
Laurent	Breuil	IMEC	Belgium
David	Brown	BAE Systems Inc.	United States
Liliana	Buda-Prejbanu	CEA	France
Fabian	Bufler	IMEC	Belgium
Erik	Bury	IMEC	Belgium

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Fuxi	Cai	Applied Materials Inc.	United States
Kaiming	Cai	IMEC	Belgium
Yimao	Cai	Peking University	China
Yong	Cai	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Cinzia	Caliendo	Istituto di Fotonica e Nanotecnologie (IFN-CNR)	Italy
Humberto	Campanella	Skyworks Solut	Singapore
Joe C.	Campbell	University of Virginia	United States
Kristy	Campbell	Boise State University	United States
Jesus	Cañas	Institut Néel	France
Giuseppe	Cantarella	Libera Università di Bolzano Facoltà di Scienze e Tecnologie	Italy
Kurtis	Cantley	Boise State University	United States
Hongtao	Cao	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Qing	Cao	University of Illinois at Urbana-Champaign	United States
Yibing	Cao	Northwest Institute of Nuclear Technology	China
Yu	Cao	Qorvo	United States
Roberto	Carboni	Politecnico di Milano	Italy
Emanuel	Carlos	CENIMAT	Portugal
Greg	Carman	University of California Los Angeles	United States
Hamilton	Carrillo Nunez	Aix-Marseille University	France
Alexandre	Carvalho	Universidade de Aveiro	Portugal
Mikael	Casse	CEA Grenoble	France
Marco	Cassinero	Politecnico di Milano	Italy
Niccolo'	Castellani	University Grenoble Alpes and CEA	France
Federica	Catania	Free University of Bozen-Bolzano	Italy
Umberto	Celano	IMEC	Belgium
Lorenzo	Cerati	STMicroelectronics SRL Sede di Agrate Brianza	Italy
Antonio	Cerdeira	CINVESTAV	Mexico
Ho-Young	Cha	Hongik University	South Korea
Kelson	Chabak	Air Force Research Laboratory	United States
Yang	Chai	Hong Kong Polytechnic University	Hong Kong
Zheng	Chai	Xi'an Jiaotong University	China
Paddy	Chan	University of Hong Kong	Hong Kong
Edward Yi	Chang	National Chiao Tung University	Taiwan
Jingjing	Chang	Xidian University	China
Jiwon	Chang	Yonsei University	South Korea
Josephine	Chang	Northrop Grumman Electronic Systems	United States
Kuan-Chang	Chang	Peking University	China
Sheng-Po	Chang	National Cheng Kung University	Taiwan
Sou-Chi	Chang	Georgia Institute of Technology	United States
Ting-Chang	Chang	National Sun Yat-sen University	Taiwan
Tzu-Hsuan	Chang	National Taiwan University	Taiwan
Wen Hsin	Chang	National Institute of Advanced Industrial Science and Technology	Japan
Kuei-Shu	Chang-Liao	National Tsing Hua University	Taiwan
Adrian	Chasin	IMEC	Belgium
Dibyendu	Chatterjee	Indian Institute of Technology Bombay	India
Reet	Chaudhuri	Cornell University	United States
Sandeep	Chaudhuri	University of South Carolina	United States
Yogesh	Chauhan	Indian Institute of Technology Kanpur	India
Wenjie	Che	New Mexico State University	United States
Nikolay G.	Chechenin	Lomonosov Moscow State University	Russia
Baile	Chen	Shanghai Tech University	China
Bing	Chen	Zhejiang University	China
Chaoping	Chen	Shanghai Jiao Tong University	United States

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Chin-Yi	Chen	Purdue University	United States
Di	Chen	Shanghai Jiao Tong University	China
Dunjun	Chen	Nanjing University	China
Edward	Chen	TSMC	Taiwan
Fan	Chen	Samsung	United States
Haibao	Chen	Shanghai Jiao Tong University	China
Jen-Sue	Chen	National Cheng Kung University	Taiwan
Jianxin	Chen	Chinese Academy of Sciences	China
Jiezhi	Chen	Shandong University	China
Jun	Chen	Sun Yat-sen University	China
Junren	Chen	Institute of Neuroinformatics	Switzerland
Kevin	Chen	Hong Kong University of Science and Technology	Hong Kong
Kuan-Neng	Chen	National Chiao Tung University	Taiwan
Lin	Chen	Fudan University	China
Lingen	Chen	Naval University of Engineering	China
Miin-Jang	Chen	National Taiwan University	Taiwan
Rongsheng	Chen	Hong Kong University of Science and Technology	Hong Kong
Rongsheng	Chen	South China University of Technology	China
Shih-Hung	Chen	IMEC	Belgium
Shuming	Chen	Southern University of Science and Technology	China
Teng-Ming	Chen	National Yang Ming Chiao Tung University	Taiwan
Wei-Chen	Chen	Macronix International Company, Ltd	Taiwan
Wei-Chen	Chen	Stanford University	United States
Weize	Chen	ON Semiconductor	United States
Xiaojie	Chen	Sichuan University	China
Yangyin	Chen	IMEC	Belgium
Yangyin	Chen	Western Digital Technologies Inc.	United States
Ying-Chen	Chen	Northern Arizona University	United States
Zhizhong	Chen	Peking University	China
Zhong	Chen	University of Arkansas	United States
Binjie	Cheng	Synopsys Inc.	United Kingdom
Buwen	Cheng	Institute of Semiconductors Chinese Academy of Sciences	China
Chun-Hu	Cheng	National Taiwan Normal University	Taiwan
I-Chun	Cheng	National Taiwan University	Taiwan
Kangguo	Cheng	IBM	United States
Ran	Cheng	Zhejiang University	China
Zhihui	Cheng	Duke University	United States
Igor	Chernyavskiy	Naval Research Laboratory	United States
Hung-Li	Chiang	Taiwan Semiconductor Manufacturing Company Ltd	Taiwan
Meng-Hsueh	Chiang	National Cheng Kung University	Taiwan
Chao-Hsin	Chien	National Chiao Tung University	Taiwan
Wei-Chih	Chien	Macronix International Company, Ltd.	Taiwan
Alessandro	Chini	University of Modena and Reggio Emilia	Italy
Hsien-Chin	Chiu	Chang Gung University	Taiwan
Sung Haeng	Cho	Electronics and Telecommunication Research Institute	South Korea
Seongjae	Cho	Gachon University	South Korea
Won-Ju	Cho	Kwangwoon University	South Korea
Vamsy	Chodavarapu	University of Chodacarapu	United States
Gihun	Choe	Georgia Institute of Technology College of Engineering	United States
Eunmi	Choi	Ulsan National Institute of Science and Technology	South Korea
Hyejeong	Choi	Yonsei University	South Korea
Rino	Choi	Inha University	South Korea
Sungju	Choi	Kookmin University	South Korea
Chi Wei	Chow	National Yang Ming Chiao Tung University	Hong Kong

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Nadim	Chowdhury	Massachusetts Institute of Technology	United States
Srabanti	Chowdhury	Stanford University	United States
Philippe	Christol	University of Montpellier	France
Alexander	Chronos	Imperial College	United Kingdom
Dewei	Chu	University of New South Wales	Australia
Rongming	Chu	Penn State University	United States
Ta-Ya	Chu	National Research Council, Canada	Canada
Kai-Hsin	Chuang	PUFsecurity Inc.	Taiwan
Eduardo	Chumbes	Raytheon Integrated Defense Systems	United States
Chin-Han	Chung	National Chiao Tung University	Taiwan
Roy	Chung	Kyungpook National University	South Korea
Robert	Coffie	RLC Solutions	United States
Oleg	Cojocari	ACST GmbH	Germany
Daniel	Connelly	University of California at Berkeley	United States
Brian	Corbett	Tyndall National Institute	Ireland
Thibault	Cosnier	IMEC	Belgium
Piero	Cosseddu	University of Cagliari	Italy
Angela	Coves	Universidad Miguel Hernández de Elche	Spain
Erika	Covi	NaMLab gGmbH	Germany
Tobias	Cramer	University of Bologna	Italy
Bogdan	Cretu	ENSICAEN	France
Bennett	Cromer	Cornell University	United States
Giovanni	Crupi	University of Messina	Italy
Edoardo	Cuniberto	New York University	United States
Maciej	Cwiklinski	Rohde und Schwarz GmbH und Company KG	Germany
Chetan	Dabhi	University of California Berkeley	United States
Gilles	Dambrine	IEMN	France
Bhaskar	Das	Indian Institute of Technology Bombay	India
Sanghamitra	Das	Silicon Institute of Technology	India
Suman	Das	Sikkim Manipal Institute of Technology	India
Avirup	Dasgupta	Indian Institute of Technology Roorkee	India
Sudeb	Dasgupta	Indian Institute of Technology Roorkee	India
Subrata	Datta	Microwave Tube Research & Development Centre	India
John	David	The University of Sheffield	United Kingdom
Sourav	De	Fraunhofer IPMS—Center Nanoelectronic Technologies CNT	Germany
Raffaele	De Rose	Universita degli Studi della Calabria	Italy
Michelly	De Souza	Centro Universitario da FEI	Brazil
Punyashloka	Debashis	Purdue University	United States
Corentin	Delacour	LIRMM	France
Quentin	Delhaye	Université Libre de Bruxelles École polytechnique de Bruxelles	Belgium
Nicholas	Dellas	Infineon Austria	Austria
Wanling	Deng	College of Information Science and Technology	China
Zhen	Deng	Institute of Physics Chinese Academy of Sciences	China
Dan	Denninghoff	Teledyne Scientific & Imaging	United States
Riccardo	Depetro	STMicroelectronics SRL Sede di Agrate Brianza	Italy
Sanchit	Deshmukh	Stanford University	United States
Veeresh	Deshpande	Helmholtz-Zentrum Berlin für Materialien und Energie GmbH	Germany
Jonas	Deuermeier	New University of Lisbon Faculty of Science and Technology	Portugal
Wouter	Devulder	IMEC	Belgium
Sarit	Dhar	Auburn University	United States
Mahmoud	Dhimish	University of Huddersfield	United Kingdom
Daryoosh	Dideban	University of Kashan	Iran

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Charalabos	Dimitriadis	Aristotle University of Thessaloniki	Greece
Jinjun	Ding	Colorado State University	United States
Shi-Jin	Ding	Fudan University	China
Xukai	Ding	Southeast University	China
Thanh Viet	Dinh	NXP Semiconductors Belgium	Belgium
José	Diniz	Universidade Estadual de Campinas, Brazil	Brazil
Guillaume	Dion	Université de Sherbrooke	Canada
Nazareno	Donato	University of Cambridge	United Kingdom
Chengyuan	Dong	Shanghai Jiao Tong University	China
Shurong	Dong	Zhejiang University	China
Shuxiang	Dong	Peking University	China
Gerben	Doornbos	TSMC	Belgium
Rodrigo	Doria	Centro Universitario da FEI	Brazil
Behnoush	Dousti	The University of Texas at Dallas	United States
Karen	Dowling	Lawrence Livermore National Laboratory	United States
Francesco	Driussi	Universita degli Studi di Udine	Italy
Chao	Du	University of Michigan	United States
Chao-Hai	Du	Peking University	China
Baoxing	Duan	Xidian University	China
Meng	Duan	Synopsys Inc.	United Kingdom
Zhaoyun	Duan	University of Electronic Science and Technology of China	China
Alexander	Dubinov	RFNC-VNIIEF	Russia
Jean-Yves	Duboz	CRHEA	France
Ray	Duffy	Tyndall National Institute	Ireland
Stefan	Dünkel	GlobalFoundries Dresden Module One LLC & Company KG	Germany
Gourab	Dutta	Indian Institute of Technology Kharagpur	India
Charvaka	Duvvury	ESD Consultant	United States
Ursula	Ebels	CNRS-CEA Spintec	France
Abasifreke	Ebong	The University of North Carolina at Charlotte	United States
Loizos	Efthymiou	University of Cambridge	United Kingdom
Mattias	Ekström	KTH Royal Institute of Technology	Sweden
Gordon	Elger	Technische Hochschule Ingolstadt	Germany
Hal	Emmer	Cambridge Electronics Inc.	United States
Kazuhiko	Endo	AIST	Japan
Geert	Eneman	IMEC	Belgium
Olof	Engström	Chalmers University of Technology	Sweden
David	Eon	Institut Néel	France
Tobias	Erlbacher	Fraunhofer Institute for Integrated Systems and Device Technology	Germany
Sukru Burc	Eryilmaz	NVIDIA Corporation	United States
Magali	Estribeau	ISAE	France
Devanarayanan	Ettisserry	Micron Technology Inc.	United States
Federico	Faccio	CERN	Switzerland
Ching-Lin	Fan	National Taiwan University of Science and Technology	Taiwan
Xin	Fan	University of Denver	United States
Zhiqiang	Fan	Northwest Institute of Nuclear Technology	China
Jingtian	Fang	Synopsys Inc.	United States
Xiaosheng	Fang	Fudan University	China
Matteo	Farronato	Polytechnic University of Milan	Italy
Patrick	Fay	University of Notre Dame	United States
Alexey	Fedotov	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Maximilian	Feil	Infineon Technologies AG	Germany

First Name	Last Name	Affiliation	Country
Jinjun	Feng	Beijing Vacuum Electronics Research Institute	China
Peijie	Feng	QUALCOMM Inc.	United States
Philip	Feng	University of Florida	United States
Claudio	Fiegna	University of Bologna	Italy
Ignasi	Fina	ICMAB	Spain
Patrick	Fiorenza	Consiglio Nazionale delle Ricerche	Italy
Massimo	Fischetti	University of Texas at Dallas	United States
Dan	Fleetwood	Vanderbilt University	United States
Andrew	Flewitt	University of Cambridge	United Kingdom
Karine	Florent	Micron Technology Inc.	United States
Xuanyao	Fong	National University of Singapore	Singapore
Stephen	Forrest	University of Michigan	United States
Ioannis	Fragkos	Lehigh University	United States
Anthony	Francis	Ozark Integrated Circuits, Inc.	United States
Jacopo	Franco	IMEC	Belgium
Aaron	Franklin	Duke University	United States
Sebastien	Fregonese	CNRS	France
Pavel	Freundlich	ON Semiconductor	United States
Martin	Frey	Synopsys Switzerland LLC	Switzerland
Peter	Friedrichs	Infineon Technologies AG	Germany
Kai	Fu	Arizona State University	United States
Wenjie	Fu	University of Electronic Science and Technology of China	China
Mami	Fujii	Nara Institute of Science and Technology	Japan
Shosuke	Fujii	Kioxia Corporation	Japan
Masahisa	Fujino	National Institute of Advanced Industrial Science	Japan
Naoto	Fujishima	Fuji Electric	Germany
Mamoru	Furuta	Kochi University of Technology	Japan
Alexander	Gabourie	Stanford University School of Engineering	United States
Anatoly	Galdetskiy	FSUE Istok	Russia
Vincent	Gambin	Northrup-Grumman Corporation	United States
Francisco	Gamiz	Universidad de Granada	Spain
Diana	Gamzina	SLAC National Accelerator Laboratory	United States
Ning	Gan	Ningbo University	China
Pratisha	Gangwar	Indian Institute of Technology Bombay	India
Bin	Gao	Tsinghua University	China
Daniele	Garbin	IMEC	Belgium
Francisco	Garcia-Sanchez	Simon Bolivar University	Venezuela
Kevin	Garello	SPINTEC	France
Xavier	Garros	CEA Grenoble	France
Lixin	Ge	QUALCOMM Inc.	United States
Michael	Geis	Massachusetts Institute of Technology	United States
Dimitra	Georgiadou	University of Southampton	United Kingdom
G�rard	Ghibaudo	IMEP-LAHC	France
Saugata	Ghose	University of Illinois Urbana-Champaign	United States
Bablu Kumar	Ghosh	Universiti Malaysia Sabah	Malaysia
Sanjay	Ghosh	Central Electronics Engineering Research Institute	India
Filippo	Giannazzo	CNR-IMM	Italy
Naum	Ginzburg	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Mikhail	Glyavin	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Michele	Goano	Politecnico di Torino	Italy
Akira	Goda	Micron Technology Inc.	United States
Vincent	Goiffon	ISAE-SUPAERO	France
Vikrant	Gokhale	US Naval Research Laboratory	United States

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Ali	Gokirmak	University of Connecticut	United States
Tayfun	Gokmen	IBM	United States
Prafful	Golani	University of Minnesota	United States
Henrique	Gomes	Univerity of the Algarve	Portugal
Roberto	Gomez-Garcia	Universidad de Alcala	Spain
Huarong	Gong	University of Electronic Science and Technology of China	China
Jiarui	Gong	University of Wisconsin-Madison	United States
Nanbo	Gong	Yale University	United States
Xiao	Gong	National University of Singapore	Singapore
Yubin	Gong	University of Electronic Science and Technology of China	China
Sujan K.	Gonugondla	Amazon.com	United States
Tomas	Gonzalez	Universidad de Salamanca	Spain
Yago	Gonzalez-Velo	Arizona State University	United States
Rupam	Goswami	KIIT University	India
Tibor	Grasser	TU Wien	Austria
Giuseppe	Greco	CNR-IMM	Italy
Andrew	Green	Air Force Research Laboratory Sensors Directorate	United States
Marty	Gregg	Queen's University Belfast	United Kingdom
Alexander	Grill	IMEC	Belgium
Vytautas	Grivickas	Vilnius University	Lithuania
Alessandro	Grossi	Infineon Technologies Italia S.r.l.	Italy
Timothy	Grotjohn	Michigan State University	United States
Shulin	Gu	Nanjing University	China
Yuandong	Gu	Shanghai University	China
Ximeng	Guan	IBM	United States
Jon Tomas	Gudmundsson	University of Iceland	Iceland
Diego	Guerra	Arizona State University	United States
Tue	Gunst	Synopsys Inc.	United States
Jing	Guo	University of Florida	United States
Liu	Guo	University of Electronic Science and Technology of China	China
Xiaojun	Guo	Shanghai Jiao Tong University	China
Yufeng	Guo	Nanjing University of Posts and Telecommunications	China
Chetan	Gupta	Indian Institute of Technology Kanpur	India
Chirag	Gupta	University of Wisconsin-Madison	United States
Geetak	Gupta	Transphorm Inc.	United States
Sumeet	Gupta	The Pennsylvania State University	United States
Edmundo	Gutiérrez-D.	Instituto Nacional de Astrofísica	Mexico
Marek	Guziewicz	Łukasiewicz Research Network—Institute of Microelectronic and Photonics	Poland
Romain	Gwoziecki	CEA-LITEN	France
Daniel	Habersat	US Army Research Laboratory	United States
Anders	Hallén	KTH Royal Institute of Technology	Sweden
Hamida	Hallil	University of Bordeaux	France
Dedong	Han	Peking University	China
Genquan	Han	Xidian University	China
Jin-Woo	Han	Samsung Electronics	South Korea
Kijeong	Han	Wolfspeed	United States
Sang-Woo	Han	Penn State University	United States
Seong-Tae	Han	Korea Electrotechnology Research Institute	South Korea
Su-Ting	Han	Shenzhen University	China
Tae-Hee	Han	Hanyang University	United States
Tao	Han	Shanghai Jiao Tong University	China
Xiaotao	Han	Huazhong University of Science and Technology	China

First Name	Last Name	Affiliation	Country
Paul	Haney	NIST Center for Nanoscale Science and Technology	United States
Yue	Hao	Xidian University	China
Kenji	Hara	Hitachi Ltd.	Japan
Matthew	Hartensveld	Rochester Institute of Technology	United States
Pouya	Hashemi	IBM	United States
Naimul	Hassan	University of Texas at Dallas	United States
Ryoma	Hayakawa	National Institute for Materials Science	Japan
Pavel	Hazdra	Czech Technical University in Prague	Czech Republic
Gang	He	Anhui University	China
Hongyu	He	Yangtze University	China
Yu-Hui	He	Huazhong University of Science and Technology	China
Chris	Heidelberg	MIT	United States
Erik	Heijne	CERN	Switzerland
Markus	Hellenbrand	Lund University	Sweden
Henning	Helmers	Fraunhofer Institute for Solar Energy Systems ISE	Germany
Robert	Henderson	University of Edinburgh	United Kingdom
Yeon-Cheol	Heo	Samsung	South Korea
Dinusha	Herath		
	Mudiyanselage	Iowa State University	United States
Sukreen Hana	Herman	Universiti Teknologi MARA	Malaysia
Lars	Heuken	Institut für Mikroelektronik Stuttgart (IMS-CHIPs)	Germany
Austin	Hickman	Cornell University	United States
Christofer	Hierold	ETH Zurich	Switzerland
Masataka	Higashiwaki	National Institute of Information and Communications Technology	Japan
Oliver	Hilt	FBH Berlin	Germany
Digh	Hisamoto	Hitachi Ltd.	Japan
Brad	Hoff	Air Force Research Laboratory	United States
Alexander	Hölke	X-FAB	Malaysia
Mark	Hollis	MIT	United States
Naoto	Horiguchi	IMEC	Belgium
Masahiro	Horita	Nagoya University	Japan
Ray-Hua	Hornng	National Chiao Tung University	Taiwan
Peter	Horoyski	Communications and Power Industries, CPI Canada	Canada
Brian	Hoskins	National Institute of Standards and Technology	United States
Hideo	Hosono	Tokyo Institute of Technology	Japan
Shuoben	Hou	II-VI (Kista)	Sweden
Tuo-Hung	Hou	National Yang Ming Chiao Tung University	Taiwan
Jan Van	Houdt	IMEC	United States
Fu	Houqiang	Iowa State University	United States
Robert	Howell	Northrop Grumman Electronic Systems	United States
Vincent K. S.	Hsiao	National Chi Nan University	Taiwan
Chia-Sheng	Hsu	Georgia Institute of Technology College of Engineering	United States
Po-Kai	Hsu	Georgia Institute of Technology	United States
Shawn	Hsu	National Tsing Hua University	Taiwan
Jie	Hu	NXP Semiconductors Austin Oak Hill	United States
Shiben	Hu	TCL China Star Optoelectronics Technology Company, Ltd	China
Vita	Hu	National Taiwan University	Taiwan
Xiaoer	Hu	University of California, Berkeley	United States
Yuanyuan	Hu	Hunan University	China
Mengyuan	Hua	Hong Kong University of Science and Technology	Hong Kong
Mengyuan	Hua	Southern University of Science and Technology	China
Qilin	Hua	Institute of Nanoenergy and Nanosystems Chinese Academy of Sciences	China
Alex	Huang	University of Texas at Austin	United States

First Name	Last Name	Affiliation	Country
Bohr-Ran	Huang	National Taiwan University of Science and Technology	Taiwan
Chih-Fang	Huang	National Tsing Hua University	Taiwan
Chun-Yuan	Huang	National Taitung University	Taiwan
Feng	Huang	Sun Yat-sen University	China
Jianjang	Huang	National Taiwan University	Taiwan
Jung-Jie	Huang	Dayeh University	Taiwan
Peng	Huang	Peking University	China
Qianqian	Huang	Peking University	China
Sen	Huang	Institute of Microelectronics of Chinese Academy of Sciences	China
Weixing	Huang	Chinese Academy of Sciences	China
Yong Mao	Huang	Xihua University	China
Yongan	Huang	Huazhong University of Science	China
Zhujun	Huang	New York University	United States
Boris	Hudec	National Chiao Tung University	Taiwan
Peter	Huggard	STFC Rutherford Appleton Laboratory	United Kingdom
Yung-Jr	Hung	National Sun Yat-sen University	Taiwan
Wenxing	Huo	The Institute of Physics, Chinese Academy of Sciences	China
Andrew	Hurrell	Precision Acoustics Ltd	United Kingdom
Louis	Hutin	CEA-Leti	France
Cheol Seong	Hwang	Seoul National University	South Korea
Hyunsang	Hwang	Pohang University of Science and Technology	South Korea
Daniele	Ielmini	Politecnico di Milano	Italy
Koichi	Iiyama	Kanazawa University	Japan
Keiji	Ikeda	Kioxia Corporation	Japan
Kiju	Im	Samsung Display Company Ltd	South Korea
Ki-Sik	Im	Kumoh National Institute of Technology	South Korea
Jean Anne	Incorvia	The University of Texas at Austin	United States
Eleftherios	Ioannidis	AMS OSRAM	Austria
Adrian Mihai	Ionescu	Swiss Federal Institute of Technology (EPFL)	Switzerland
Koichi	Ishida	Technische Universitaet Dresden	Germany
Kazunari	Ishimaru	Kioxia Corporation	Japan
Ahmad	Islam	Air Force Research Laboratory Materials and Manufacturing Directorate	United States
Raisul	Islam	Stanford University	United States
Noriyuki	Iwamuro	Tsukuba Daigaku	Japan
Ruchil	Jain	GlobalFoundries Inc.	Singapore
Vibhor	Jain	IBM	United States
Michael Paul	Jallorina	Nara Sentan Kagaku Gijutsu Daigakuin Daigaku Busshitsu Sosei Kagaku Kenkyuka	Japan
Alex	James	Digital University Kerala	India
Raj	Jana	JANA Research Initiative	United States
Jaewon	Jang	Kyungpook National University	South Korea
Jin	Jang	Kyung Hee University	South Korea
Deep	Jariwala	University of Pennsylvania	United States
Himani	Jawa	Indian Institute of Technology Bombay	India
John	Jelonnek	Karlsruhe Institute of Technology	Germany
Biswajit	Jena	VIT University	India
Kevin	Jensen	Naval Research Laboratory	United States
Jongwook	Jeon	Konkuk University	South Korea
Jae Kyeong	Jeong	Hanyang University	South Korea
Dong	Ji	Stanford University	United States
Zhigang	Ji	Shanghai Jiao Tong University	China
Renxu	Jia	Xidian University	China
Chao	Jiang	National Center for Nanoscience and Technology	China

First Name	Last Name	Affiliation	Country
Chen	Jiang	Tsinghua University	China
Hao	Jiang	Fudan University	China
Huaxing	Jiang	The Hong Kong University of Science and Technology	Hong Kong
Jie	Jiang	Central South University	China
Pei-Hsun	Jiang	National Taiwan Normal University	Taiwan
Qimeng	Jiang	Chinese Academy of Sciences	China
Sheng	Jiang	Northwestern Polytechnical University	China
Sheng	Jiang	University of Gothenburg	Sweden
Yu-Long	Jiang	Fudan University	China
Hailong	Jiao	Peking University Shenzhen Graduate School	China
Chengji	Jin	Institute of Industrial Science, The University of Tokyo	Japan
Jidong	Jin	Hanyang University—Education Research Industry Cluster at Ansan	South Korea
Lei	Jin	Institute of Microelectronics of Chinese Academy of Sciences	China
Seonghoon	Jin	Samsung Semiconductor Inc.	United States
Yizheng	Jin	Zhejiang University	China
Yufeng	Jin	Shenzhen Graduate School of Peking University	China
Sameer	Joglekar	Intel Corporation	United States
Jungwoo	Joh	Texas Instruments	United States
Rohit	John	ETH Zürich	Switzerland
David	Johnsson	Intel Mobile Communications	Germany
Chandan	Joishi	The Ohio State University	United States
Saumil	Joshi	Micron Technology Inc.	United States
Ravi	Joshi	Texas Tech University	United States
Jinchuan	Ju	National University of Defense Technology	China
Christoph	Jungemann	RWTH Aachen University	Germany
Pilin	Junsangsri	Wentworth Institute of Technology	United States
Ben	Kaczer	IMEC	Belgium
Bhagyalakshmi	Kakarla	ETH Zurich	Switzerland
Shoji	Kakio	Yamanashi Daigaku—Kofu Campus	Japan
Anisha	Kalra	Indian Institute of Science	India
Masakazu	Kanechika	Toyota Central Research and Development Labs., Inc.	Japan
Hyemin	Kang	Korea Institute of Energy Technology (KENTECH)	South Korea
Jinfeng	Kang	Peking University	China
Kuo-Hsing	Kao	National Cheng Kung University	Taiwan
Ming-Yen	Kao	University of California Berkeley	United States
Robert	Kaplar	Sandia National Labs	United States
Ilya	Karpov	Intel Corporation	United States
Victor	Karpov	University of Toledo	United States
Makoto	Kasu	Saga University	Japan
Ankit	Kaul	Georgia Institute of Technology College of Engineering	United States
Harsupreet	Kaur	University of Delhi	India
Jamil	Kawa	Synopsys Inc.	United States
Hiroshi	Kawarada	Waseda University	Japan
Suzuki	Kazuhiko	Hokkaido University of Science	Japan
John	Kennedy	National Isotope Centre	New Zealand
Ming-Dou	Ker	National Yang Ming Chiao Tung University	Taiwan
Vishal	Kesari	Microwave Tube Research & Development Centre	India
Dolar	Khachariya	North Carolina State University	United States
Wan	Khairul	Universiti Malaysia Terengganu	Malaysia
Ali	Khakifirooz	Intel Corporation	United States
Asif	Khan	Georgia Institute of Technology	United States
Asir Intisar	Khan	Stanford University	United States

First Name	Last Name	Affiliation	Country
Hassan	Khan	Lahore University of Management Sciences	Pakistan
Akif Aabrar	Khandker	University of Notre Dame	United States
Abhishek	Khanna	University of Notre Dame	United States
Michael	Khazhinsky	Silicon Labs	United States
Afreen	Khursheed	Maulana Azad National Institute of Technology	India
Asal	Kiazadeh	CENIMAT	Portugal
Choong-Ki	Kim	SK hynix Inc.	South Korea
Dae Hwan	Kim	Kookmin University	South Korea
Dae Yeon	Kim	The University of Texas at Dallas	United States
Deok-Kee	Kim	Sejong University	South Korea
Dong Myong	Kim	Kookmin University	South Korea
Garam	Kim	Myongji University—Natural Science Campus	South Korea
Hogyoung	Kim	Seoul National University of Science and Technology	South Korea
Hyun Jae	Kim	Yonsei University	South Korea
Hyungjin	Kim	Inha University	South Korea
Hyun-Seop	Kim	University of Bristol	United Kingdom
Jeonghoon	Kim	University of California San Diego	United States
Junghwan	Kim	Tokyo Institute of Technology	Japan
Myunggil	Kim	Sung Kyun Kwan University	South Korea
Sangbum	Kim	Seoul National Univeristy	South Korea
Sang-Hyeon	Kim	Korea Institute of Science and Technology	South Korea
Sang-Jae	Kim	Jeju National University	South Korea
Sangwan	Kim	Sogang University	South Korea
Sang-Woo	Kim	Sungkyunkwan University	South Korea
Seyoung	Kim	Pohang University of Science and Technology	South Korea
Tae-Hyeon	Kim	Seoul National University	South Korea
Yong-Sang	Kim	Sungkyunkwan University	South Korea
Yoon	Kim	University of Seoul	South Korea
Tsunenobu	Kimoto	Kyoto University	Japan
Kei	Kimura	Sony Group Corporation Atsugi Technology Center	Japan
Mutsumi	Kimura	Ryukoku University	Japan
Dmitry	Kireev	University of Texas at Austin	United States
Koji	Kita	The University of Tokyo	Japan
Hagen	Klauk	Max Planck Institute for Solid State Research	Germany
Tihomir	Knezevic	Ruder Boskovic Institute	Croatia
Seung Hwan	Ko	Seoul National University	South Korea
Petia	Koprinkova-Hristova	Bulgarian Academy of Sciences	Bulgaria
Selcuk	Kose	University of Rochester	United States
Roza	Kotlyar	Intel Corporation	United States
Randy	Koval	Intel Corporation	United States
Abhinav	Kranti	Indian Institute of Technology (IIT) Indore	India
Abhinav	Kranti	Indian Institute of Technology Indore	India
Yakov	Krasik	Technion—Israel Institute of Technology	Israel
Hannes	Kraus	NASA Jet Propulsion Laboratory	United States
Sriram	Krishnamoorthy	UC Santa Barbara	United States
Zoran	Krivokapic	Advanced Micro Devices Inc.	United States
Martin	Kuball	University of Bristol	United Kingdom
Toshiharu	Kubo	Nagoya Insitute of Technology	Japan
Kelin	Kuhn	Cornell University	United States
Bohdan	Kulyk	University of Aveiro	Portugal
B Sampath	Kumar	Indian Institute of Science	India
Durgesh	Kumar	Nanyang Technological University	Singapore
M. Jagadesh	Kumar	Indian Institute of Technology	India
Priyadarshi	Kumar	Indian Institute of Technology Bombay	India
Shashi	Kumar	National Institute of Technology Meghalaya	India

First Name	Last Name	Affiliation	Country
Yusuke	Kumazaki	Fujitsu Ltd	Japan
Sandip	Kundu	University of Massachusetts System	United States
Kakushima	Kuniyuki	Tokyo Institute of Technology	Japan
Hao-Chung	Kuo	National Chiao Tung University	Taiwan
Yue	Kuo	Texas A&M University	United States
Shin-Ichiro	Kuroki	Hiroshima University	Japan
Rambabu	Kusuma	National Institute of Technology Warangal	India
Masaaki	Kuzuhara	Kwansei Gakuin University	Japan
Jeonghun	Kwak	Seoul National University	South Korea
Joon Seop	Kwak	KENTECH	South Korea
Dae Woong	Kwon	Inha University	South Korea
Hyuck-In	Kwon	Chung-Ang University	South Korea
Jimin	Kwon	Pohang University of Science and Technology	South Korea
Oh-Kyong	Kwon	Hanyang University	South Korea
Uihui	Kwon	Samsung Electronics	South Korea
Avinash	Lahgere	Indian Institute of Technology Kanpur	India
Oliver	Lahr	Universität Leipzig	Germany
Chao Sung	Lai	Chang Gung University	Taiwan
Stefano	Lai	Università di Cagliari	Italy
Wei-Chih	Lai	National Cheng Kung University	Taiwan
Rakesh	Lal	Transphorm Inc.	United States
Linfeng	Lan	South China University of Technology	China
Yann-Wen	Lan	National Taiwan Normal University	Taiwan
Mario	Lanza	King Abdullah University of Science and Technology	Saudi Arabia
Luca	Larcher	Applied Materials Inc.	United States
Sandip	Lashkare	Indian Institute of Technology Bombay	India
Mario	Laudato	Intermolecular Inc.	United States
Nicolas	Laurand	University of Strathclyde	United Kingdom
Bongmook	Lee	North Carolina State University	United States
Byoung Hun	Lee	Pohang University of Science and Technology	South Korea
Chengkuo	Lee	National University of Singapore	Singapore
Choong Hyun	Lee	The University of Tokyo	Japan
Czang-Ho	Lee	University of Waterloo	Canada
Daeseok	Lee	Kwangwoon University	South Korea
Hyeon-Jun	Lee	Daegu Gyeongbuk Institute of Science and Technology	South Korea
Hyung-Seok	Lee	Electronics and Telecommunications Research Institute	South Korea
Hyunjea	Lee	Cornell University	United States
Jaehyun	Lee	Synopsys Inc.	United Kingdom
Jaeseob	Lee	Samsung Display Company Ltd	South Korea
Jang-Sik	Lee	Pohang University of Science and Technology	South Korea
Jeong-Soo	Lee	Pohang University of Science and Technology	South Korea
Jong-Ho	Lee	Seoul National University	South Korea
Joshua	Lee	Institute of Microelectronics	Singapore
Kuan-Wei	Lee	I-Shou University	Taiwan
Kung-Yen	Lee	National Taiwan University	Taiwan
Min-Hung	Lee	National Taiwan Normal University	Taiwan
Rinus	Lee	GlobalFoundries Inc.	United States
Sanghyo	Lee	University of Cambridge	United Kingdom
Sungsik	Lee	Pusan National University	South Korea
Tae-Woo	Lee	Seoul National University	South Korea
Yao-Jen	Lee	Taiwan Semiconductor Research Institute	Taiwan
Yih-Shing	Lee	Minghsin University of Science & Technology	Taiwan
Alberto	Leggieri	Università degli studi di Roma "Tor Vergata"	Italy
Wei	Lei	Southeast University	China
Jaakko	Leppäniemi	VTT Technical Research Center of Finland	Finland

First Name	Last Name	Affiliation	Country
Aidong	Li	Nanjing University	China
Baikui	Li	Shenzhen University	China
Bo	Li	Institute of Microelectronics of Chinese Academy of Sciences	China
Bochang	Li	Xidian University	China
Can	Li	University of Hong Kong	Hong Kong
Cheng	Li	University of California Riverside	United States
Cheng	Li	Xiamen University	China
Dabing	Li	Changchun Institute of Optics Fine Mechanics and Physics Chinese Academy of Sciences	China
Haitong	Li	Purdue University	United States
Huanglong	Li	Tsinghua University	China
Jiun-Yun	Li	National Taiwan University	Taiwan
Jun	Li	Shanghai university	China
Ling	Li	Institute of Microelectronics	China
Liqiang	Li	Tianjin University	China
Mengjiao	Li	University of Southern California	United States
Ming-Huang	Li	National Tsing Hua University	Taiwan
Ming-Jui	Li	Georgia Institute of Technology	United States
Shaojuan	Li	Changchun Institute of Optics Fine Mechanics and Physics Chinese Academy of Sciences	China
Wei	Li	Shaanxi University of Science & Technolog	United States
Wei-Chang	Li	NTU College of Engineering	Taiwan
Wenshen	Li	Cornell University	United States
Xianbo	Li	Sun Yat-sen University	China
Xiangdong	Li	Xidian University	China
Xifeng	Li	Shanghai University	China
Xueqing	Li	Tsinghua University	China
Yan-Qing	Li	East China Normal University Liyan	China
Yi	Li	Huazhong University of Science and Technology	China
Yingtao	Li	Lanzhou University	China
Yiyang	Li	Univesity of Michigan	United States
Yuzhi	Li	South China University of Technology	China
Zehong	Li	University of Electronic Science and Technology of China	China
Lin	Liang	Huazhong University of Science and Technology	China
Wei	Liang	Globalfoundries Inc.	United States
Zongcun	Liang	Sun Yat-sen University	China
Congwei	Liao	Peking University	China
Lei	Liao	Hunan University	China
Lei	Liao	Wuhan University	China
Meiyong	Liao	National Institute for Materials Science	Japan
Milton	Liao	National Taiwan University	Taiwan
Min	Liao	Xiangtan University	China
Daniel	Lichtenwalner	Wolfspeed	United States
Bohan	Lin	Tsinghua University	China
Chien-Chung	Lin	National Chiao Tung University College of Photonics	Taiwan
Chih-Lung	Lin	National Cheng Kung University	Taiwan
Chun	Lin	National Chiao Tung University	Taiwan
Dong	Lin	Jimei University	China
Hornng-Chih	Lin	National Chiao Tung University	Taiwan
Jing-Yu	Lin	South China University of Technology	China
Po Jung	Lin	Global Wafers Company Ltd	Taiwan
Xi-Wei	Lin	Synopsys Inc.	United States
Ya	Lin	Northeast Normal University	China
Yen-Kai	Lin	Samsung Semiconductor Inc. USA	United States

First Name	Last Name	Affiliation	Country
Yo-Shen	Lin	National Central University	Taiwan
Yuxuan	Lin	MIT	United States
Zehao	Lin	Purdue University	United States
Erik	Lind	Lund University	Sweden
Alvydas	Lisauskas	Frankfurt University	Germany
Chee Wee	Liu	National Taiwan University	Taiwan
Chuan	Liu	Sun Yat-sen University	China
Dong	Liu	University of Wisconsin-Madison	United States
Fang	Liu	Tsinghua University	China
Gang	Liu	Shanghai Jiao Tong University	China
Haitao	Liu	Micron Technology Inc.	United States
Han-Yin	Liu	National Sun Yat-sen University	Taiwan
Jia-Zhe	Liu	Global Wafers Company Ltd	Taiwan
Jing	Liu	Tianjin University	China
Ming	Liu	Institute of Microelectronics of Chinese Academy of Sciences	China
Po-Tsun	Liu	National Chiao Tung University	Taiwan
Samuel	Liu	The University of Texas at Austin	United States
Tong	Liu	Micron Technology Inc.	United States
Wen	Liu	Xi'an Jiaotong-Liverpool University	China
Wenxin	Liu	Institute of Electronics, CAS	China
Xian	Liu	Silicon Storage Technolog	United States
Xinke	Liu	Shenzhen University	China
Xizhe	Liu	Jilin University	China
Xueqing	Liu	Rensselaer Polytechnic Institute	United States
Yong	Liu	Hong Kong University of Science and Technology	Hong Kong
Yuhuai	Liu	Zhengzhou University	China
Zhan	Liu	Intel Corporation	United States
Zhaojun	Liu	Southern University of Science and Technology	China
Zhenbang	Liu	Institute of Applied Electronics, China Academy of Engineering Physics	China
Zhihong	Liu	Singapore-MIT Alliance for Research and Technology	Singapore
Guo-Qiang	Lo	Adv Micro Foundry	United States
Yu-Hwa	Lo	University of California San Diego	United States
Patrick	Lomenzo	NaMLab gGmbH	Germany
Shibing	Long	University of Science and Technology of China	China
Neophytos	Lophitis	University of Nottingham	United Kingdom
Leo	Lorenz	Infineon Technologies China Company Ltd	China
Liang	Lou	Shanghai Industrial μ Technology Research Institute	China
Nicolas	Loubet	IBM	United States
Anni	Lu	Georgia Institute of Technology College of Engineering	United States
Darsen	Lu	National Cheng Kung University	Taiwan
Hai	Lu	Nanjing University	China
James J.-Q.	Lu	Rensselaer Polytechnic Institute	United States
Jiang	Lu	Institute of Microelectronics of Chinese Academy of Sciences	China
Lei	Lu	Hong Kong University of Science and Technology	Hong Kong
Lei	Lu	Peking University	China
Tao-Cheng	Lu	Macronix International Company Ltd.	Taiwan
Xing	Lu	Sun Yat-sen University	China
Yipeng	Lu	University of California, Davis	United States
Mathieu	Luisier	ETH Zurich	Switzerland
Mark	Lundstrom	Purdue University	United States
Guang-Li	Luo	National Nano Device Laboratories	Taiwan
Guo-Lun	Luo	University of California, Davis	United States

First Name	Last Name	Affiliation	Country
Jingting	Luo	Shenzhen University	China
Jirun	Luo	Institute of Electronics	China
Jun	Luo	The Institute of Microelectronics of Chinese Academy of Science	China
Linbao	Luo	Hefei University of Technology	China
Qing	Luo	Institute of Microelectronics of Chinese Academy of Sciences	China
Xiao Rong	Luo	University of Electronic Science and Technology of China	China
Yuan-Chun	Luo	Georgia Institute of Technology	United States
Zhaochun	Luo	Peking University	China
Zhengdong	Luo	Xidian University	China
Rudi	Lussana	Politecnico di Milano	Italy
Josef	Lutz	Chemnitz University of Technology	Germany
Hangbing	Lv	Institute of Microelectronics of Chinese Academy of Sciences	China
Yuanjie	Lv	Hebei Semiconductor Research Institute	China
Alexander	Lyublinsky	Physical-Technical Institute	Russia
Xiaohua	Ma	Xidian University	China
Xio	Ma	Qorvo	United States
Zhenqiang (Jack)	Ma	University of Wisconsin-Madison	United States
Oreste	Madia	Taiwan Semiconductor Manufacturing Company Europe BV	Belgium
Takuya	Maeda	Cornell University	United States
Takuya	Maeda	Kyoto University	Japan
Bikram	Mahajan	Purdue University	United States
Santanu	Mahapatra	Indian Institute of Science	India
Souvik	Mahapatra	Indian Institute of Technology Bombay	India
Peyman	Mahouti	Istanbul Cerrahpas University	United States
Siddheswar	Maikap	Chang Gung University	Taiwan
Luca	Maiolo	CNR	Italy
Santanu	Maity	Indian Institute of Engineering Science and Technology	India
Shubhankar	Majumdar	National Institute of Technology Meghalaya	India
Swatilekha	Majumdar	IMEC	Belgium
B. Gunnar	Malm	Kungliga Tekniska Hogskolan	Sweden
Anna	Malmros	Chalmers University of Technology	Sweden
Timothy	Maloney	Intel Corporation	United States
Cristell	Maneux	Université de Bordeaux	France
Alan	Mantooth	University of Arkansas	United States
Tomas	Manzaneque Garcia	Delft University of Technology	The Netherlands
Hongying	Mao	Hangzhou Normal University	China
Luigi	Mariucci	Consiglio Nazionale delle Ricerche	Italy
Antonio	Martinez	Swansea University	United Kingdom
Diego	Martín-Martín	Universidad Rey Juan Carlos	Spain
Jorge	Martins	CENIMAT	Portugal
Rodrigo	Martins	Universidade Nova de Lisboa	Portugal
Marta	Mas-Torrent	Instituto de Ciencia de Materiales de Barcelona	Spain
Jimson	Mathew	Indian Institute of Technology Patna	India
Elison	Matioli	École Polytechnique Fédérale de Lausanne	Switzerland
Mallory	Mativenga	Kyung Hee University	South Korea
Tomoko	Matsudai	Toshiba Corporation	Japan
Hiroyuki	Matsui	Yamagata University—Yonezawa Campus	Japan
Narasimha Rao	Mavilla	Synopsys India Pvt. Ltd	India
Sergey	Maximenko	US Naval Research Laboratory	United States
Sudip	Mazumder	University of Illinois	United States

First Name	Last Name	Affiliation	Country
Colin	Mcandrew	NXP Semiconductors NV	United States
Connor	McClellan	Stanford University	United States
Farid	Medjdoub	CNRS Délégation Ile-de-France Ouest et Nord	France
Adnan	Mehonic	UCL	United Kingdom
Saumitra	Mehrotra	Maxim Integrated	United States
Zengxia	Mei	Institute of Physics Chinese Academy of Sciences	China
Tilo	Meister	Technische Universität Dresden	Germany
Matteo	Meneghini	University of Padova	Italy
Stephan	Menzel	Forschungszentrum Julich GmbH	Germany
Meyya	Meyyappan	NASA Ames Research Center	United States
Shinji	Migita	AIST	Japan
Slobodan	Mijalkovic	Silvaco Europe	United Kingdom
Thomas	Mikolajick	Technische Universität Dresden	Germany
Nicholas	Miller	Air Force Research Laboratory	United States
Takanori	Mimura	Gakushuin University	Japan
Sun-Hong	Min	Seoul National University	South Korea
Takeo	Minari	MANA-NIMS	Japan
Guru	Mishra	National Institute of Technology	India
Varun	Mishra	Intel Corporation	United States
Tomohiko	Mitani	Kyoto University	Japan
Arkadeep	Mitra	The University of Texas at Dallas	United States
Sushant	Mittal	Indian Institute of Technology Varanasi	India
Yasuyuki	Miyamoto	Tokyo Institute of Technology	Japan
Makoto	Miyoshi	Nagoya Institute of Technology	Japan
Fei	Mo	Kioxia Corporation	Japan
Stefan	Moench	Fraunhofer-Institut für Angewandte Festkörperphysik	Germany
Peter	Moens	ON Semiconductor	Belgium
Suzanne	Mohney	Penn State University	United States
Majid	Mohseni	Shahid Beheshti University	Iran
Joel	Molina	INAOE	Mexico
Sandip	Mondal	Indian Institute of Science	India
Dong-Il	Moon	NASA Ames Research Center	United States
Yi-Shien	Mor	TSMC	Taiwan
David	Moran	University of Glasgow	United Kingdom
Nobuya	Mori	Osaka University	Japan
Zohreh	Movahedian	Shahrood University of Technology	Iran
Hema	Movva	University of Texas at Austin	United States
Sivakumar	Mudanai	Intel Corporation	United States
Adnan	Mujahid	Punjab University	Pakistan
Shaibal	Mukherjee	Indian Institute of Technology Indore	India
Subhadeep	Mukhopadhyay	Intel Corporation	United States
Halid	Mulaosmanovic	GlobalFoundries Inc.	Germany
Niko	Münzenrieder	Free University of Bozen-Bolzano	Italy
Paul	Muralt	École Polytechnique Fédérale de Lausanne	Switzerland
Andrey	Muraviev	University of Central Florida	United States
Roberto Stack	Murphy-Arteaga	National Inst for Astrophysics Optics and Electronics	Mexico
Karthick	Murugesan	University of Cambridge	United Kingdom
Artem	Musienko	Helmholtz-Zentrum Berlin für Materialien und Energie GmbH	Germany
Sanghoon	Myung	Samsung Electronics Device Solutions	South Korea
Harsh	Naik	Infineon Technologies Americas Corporation	United States
Pradeep	Nair	Indian Institute of Technology Bombay	India
Satoshi	Nakazawa	Panasonic Corporation	Japan
Tianxiang	Nan	Tsinghua University	China
Lis	Nanver	University of Twente	The Netherlands
Rakhi	Narang	University of Delhi	India

First Name	Last Name	Affiliation	Country
Aravind	Narayanan	Tokyo Institute of Technology	Japan
Sudarshan	Narayanan	Western Digital Technologies Inc.	United States
Federico	Nardi	Applied Materials Inc.	United States
Digbijoy	Nath	Indian Institute of Science	India
Gabriele	Navarro	CEA-LETI MINATEC	France
Nupur	Navlakha	University of Texas at Austin	United States
Luca	Nela	École Polytechnique Fédérale de Lausanne	Switzerland
Philip	Neudeck	NASA	United States
Geok Ing	Ng	Nanyang Technological University	Singapore
Tien Khee	Ng	King Abdullah University of Science and Technology	Saudi Arabia
Wai Tung	Ng	University of Toronto	Canada
Thanh	Nguyen	Griffith University Griffith Sciences	Australia
Kai	Ni	Vanderbilt University	United States
Gianluca	Nicosia	Micron Technology Inc.	United States
Dmitri	Nikonov	Intel Corporation	United States
Hussein	Nili	University of California Santa Barbara	United States
Hong-Long	Ning	South China University of Technology	China
Zhijun	Ning	Shanghai Tech University	China
Tomonori	Nishimura	The University of Tokyo	Japan
Tatsuya	Nishiwaki	Toshiba Semiconductor Company	Japan
Iulian	Nistor	mqSemi AG	Switzerland
Guofu	Niu	Auburn University	United States
Zhichuan	Niu	State Key Laboratory for Superlattices and Microstructures	China
Kazuki	Nomoto	Cornell University	United States
Kenji	Nomura	University of California San Diego	United States
Arto	Nurmikko	Brown University	United States
Gregory	Nusinovich	University of Maryland	United States
Borna	Obradovic	TCAD	United States
Shunri	Oda	Tokyo Institute of Technology	Japan
Dongyeon	Oh	Hynix Semiconductor Inc.	South Korea
Saeroonter	Oh	Hanyang University	South Korea
Sangheon	Oh	University of California San Diego	United States
Shun-Ichiro	Ohmi	Tokyo Institute of Technology—Suzukakedai Campus	Japan
Hiromichi	Ohta	Hokkaido University	Japan
Toshiyuki	Oishi	Saga University	Japan
Aaron	Okie	Northrop Grumman Space Technology	United States
Phil	Oldiges	Sandia National Laboratories	United States
Marius	Orlowski	Virginia Tech	United States
Adelmo	Ortiz-Conde	Universidad Simon Bolivar	Venezuela
Clemens	Ostermaier	Infineon Technologies	Austria
Vaibhav	Ostwal	Purdue University	United States
Hiroyuki	Ota	National Institute of Advanced Industrial Science and Technology	Japan
Jack	Ou	California State University Northridge	United States
Anibal	Pacheco-Sanchez	Autonomous University of Barcelona	Spain
Pradeep	Pai	Intel Corporation	United States
Marco	Pala	Centre de Nanosciences et Nanotechnologies	France
Pierpaolo	Palestri	Universita degli Studi di Udine	Italy
Emiliano	Pallecchi	IEMN	France
Feng	Pan	Tsinghua University	China
Liyang	Pan	Tsinghua University	China
Tung-Ming	Pan	Chang Gung University	Taiwan
Amritanshu	Pandey	Indian Institute of Technology	India
Shesh Mani	Pandey	GlobalFoundries	Singapore
Danilo	Pani	University of Cagliari	Italy

First Name	Last Name	Affiliation	Country
Claudio	Paoloni	Lancaster University	United Kingdom
Jin-Seong	Park	Hanyang University	South Korea
Jun-Young	Park	Chungbuk National University	South Korea
Keechan	Park	Konkuk University	South Korea
Min Hyuk	Park	Seoul National University	South Korea
Min Hyuk	Park	Pusan National University	South Korea
Min-Kyu	Park	Seoul National University	South Korea
Minseo	Park	Auburn University	United States
Sang-Hee	Park	KAIST	South Korea
Sung Kyu	Park	Chung-Ang University	South Korea
Shubhra	Pasayat	University of Wisconsin-Madison	United States
John	Pasour	Naval Research Laboratory	United States
Bishnu	Patra	Intel Corporation	United States
Erin	Patrick	University of Florida	United States
Paolo	Pavan	Universita di Modena e Reggio Emilia	Italy
Marcelo	Pavanello	Centro Universitario da FEI	Brazil
Stephen	Pearton	University of Florida	United States
Vincenzo	Pecunia	Simon Fraser University	Canada
Vladimir	Pejovic	IMEC	Belgium
Sara	Pellegrini	STMicroelectronics	United Kingdom
Chao	Peng	China Electronic Product Reliability and Environmental Testing Research Institute	China
Lan	Peng	IMEC	Belgium
Yue	Peng	Xidian University	China
Ashish Verma	Penumatcha	Intel Corporation	United States
Oleg	Penzin	Synopsys Inc.	United States
Luis	Pereira	Universidade Nova de Lisboa FCT	Portugal
Julien	Pernot	Institut Néel	France
Joshua	Perozek	Massachusetts Institute of Technology	United States
Komalan	Perumkunnil	IMEC	Belgium
Milan	Pešić	Applied Materials Inc.	United States
Nikolai	Peskov	Russian Academy of Sciences	Russia
Rebecca	Peterson	University of Michigan	United States
Luisa	Petti	Libera Università di Bolzano	Italy
Jonathan	Petticrew	University of Sheffield	United Kingdom
Martin	Pfost	Technische Universität Dortmund	Germany
Gianluca	Piazza	Carnegie Mellon University	United States
Enrico	Piccinini	ARCES Research Center	Italy
Daniel	Piedra	Analog Devices Inc. Wilmington	United States
Maykel	Piedrahita	Universidad de Guadalajara	Mexico
Dominique	Planson	Université de Lyon	France
Dionyz	Pogany	Vienna University of Technology	Austria
Antonio	Politano	University of L'Aquila	Italy
Mirko	Poljak	University of Zagreb	Croatia
Niels	Posthuma	IMEC	Belgium
Ghobad Behzadi	Pour	Islamic Azad University	Iran
Ali	Pourghaderi	Samsung Electronics	South Korea
Amit	Prakash	Crossbar Inc.	United States
Chetan	Prasad	Intel Corporation	United States
Tatiana	Prutskij	Benemérita Universidad Autónoma de Puebla	Mexico
Francesco Maria	Puglisi	Universita' di Modena e Reggio Emilia	Italy
Joaquim	Puigdollers	Universitat Politècnica Catalunya	Spain
Yinghua	Qiu	Shandong University	China
Rüdiger	Quay	Fraunhofer IAF	Germany
Ujwal	Radhakrishna	Indian Institute of Technology Madras	India
Bruce	Rae	STMicroelectronics	United Kingdom

First Name	Last Name	Affiliation	Country
Nagarajan	Raghavan	Singapore University of Technology & Design	Singapore
Shyam	Raghunathan	Micron Technology Inc.	Singapore
Nivedita	Rai	Indian Institute of Technology Indore	India
Aditya	Raj	University of California Santa Barbara	United States
Nitin	Rajan	University of California at Santa Barbara	United States
S. Srinivasulu	Raju	National Institute of Technology (NIT System)	India
Shriram	Ramanathan	Purdue University	United States
Sivaramakrishnan	Ramesh	IMEC	Belgium
Stephen	Ramey	Intel Corporation	United States
Vikas	Rana	STMicroelectronics pvt Ltd Greater Noida	India
Sanjay	Rangan	Intel Corporation	United States
Arman	Rashid	University of Arkansas Fayetteville	United States
Joseph Daniel	Rathnasami	Annamalai University	India
Pramod	Reddy	North Carolina State University	United States
William	Redman-White	University of Southampton	United Kingdom
Susanna	Reggiani	Università di Bologna	Italy
David	Reid	Synopsys Inc.	United States
Chenhao	Ren	University of California Davis	United States
Na	Ren	Zhejiang University	China
Zeyang	Ren	Xidian University	China
Pavel Ivanoff	Reyes	Rutgers State University New Brunswick	United States
Reto	Rhyner	Synopsys Switzerland LLC	Switzerland
Aditya	Rianjanu	Inst Teknol Sumatera	Indonesia
Craig	Riddet	Synopsys Inc.	United Kingdom
Denis	Rideau	STMicroelectronics	France
Rafael	Rios	Samsung	United States
Serena	Rizzolo	Airbus Defence and Space SAS	France
Patrick	Roblin	Ohio State University	United States
Fabrizio	Roccaforte	CNR-IMM	Italy
Michael	Rodder	University of Texas at Austin	United States
Noel	Rodriguez	Universidad de Granada	Spain
Albert	Roitman	Communications and Power Industries	Canada
Brian	Romanczyk	University of California, Santa Barbara	United States
Tabrizian	Roosbeh	University of Florida	United States
Niklas	Rorsman	Chalmers University of Technology	Sweden
Vladislav	Rostov	Institute of High Current Electronics	Russia
Nicolas	Rouger	CNRS	France
Francois	Roy	STMicroelectronics	France
Vellaisamy	Roy	City University of Hong Kong	Hong Kong
Andrey	Rozhnev	Instituta radiotehniki i elektroniki Saratovskij filial	Russia
Cunjun	Ruan	Beihang University	China
Phil	Rutter	iDEAL Semiconductor	United States
Nikita	Ryskin	Russian Academy of Sciences	Russia
Sei-Hyung	Ryu	Wolfspeed, Inc.	United States
Ali	Saadat	University of Texas at Dallas	United States
Svilen	Sabchevski	Balgarska akademija na naukite	Bulgaria
Angada	Sachid	Applied Materials Inc.	United States
Angada B.	Sachid	University of California Berkeley	United States
Sharif Md	Sadaf	INRS	United States
Sunny	Sadana	Indian Institute of Technology Bombay	India
Dipankar	Saha	Indian Institute of Technology Bombay	India
Samar K.	Saha	Prospicient Devices	United States
Shubham	Sahay	Indian Institute of Technology Kanpur	India
Wataru	Saito	Kyushu University	Japan
Shigeki	Sakai	National Institute of Advanced Industrial Science and	Japan
Jayatika	Sakhujia	Indian Institute of Technology Bombay	India

First Name	Last Name	Affiliation	Country
Katsuyuki	Sakuma	IBM	United States
Sayeeef	Salahuddin	University of California, Berkeley	United States
Rakshith	Saligram	Georgia Institute of Technology	United States
Stefano	Salvatori	Universita degli Studi Niccolo Cusano	Italy
Subhranu	Samanta	National University of Singapore	Singapore
Mohammad	Samizadeh Nikoo	École Polytechnique Fédérale de Lausanne	Switzerland
Sergey	Samsonov	Institute of Applied Physics	Russia
Venkateswarlu	Sankatali	IMEC	Belgium
Saurabh	Sant	Indian Institute of Technology Bombay	India
Vivek	Saraswat	Indian Institute of Technology Bombay	India
Vivek	Saraswat	University of Wisconsin-Madison	United States
Kohei	Sasaki	Novel Crystal Technology	Japan
Nandakumar	Sasidharan		
	Rajalekshmi	IBM	Switzerland
Jagabar	Sathik	SRM Institute of Science and Technology	India
Alexander	Satka	Slovak University of Technology	Slovakia
Shin-Ichiro	Sato	Japan Atomic Energy Agency	Japan
Matlabjon	Sattorov	Seoul National University	South Korea
Paul	Saunier	Qorvo	United States
Sneh	Saurabh	Indraprastha Institute of Information Technology	India
Andrey	Savilov	Institute for Applied Physics	Russia
Tanuj	Saxena	NXP Semiconductors	United States
Shehrin	Sayed	University of California Berkeley	United States
Edl	Schamiloglu	University of New Mexico	United States
Alexander	Schmidt	Samsung Electronics	South Korea
Jurriaan	Schmitz	University of Twente	The Netherlands
Harald	Schneider	Helmholtz-Zentrum Dresden-Rossendorf	Germany
Andries	Scholten	NXP Semiconductors	The Netherlands
Ronald	Schrimpf	Vanderbilt University	United States
Patrick	Schuh	Hensoldt Sensors GmbH	Germany
Fabio	Sebastiano	Technische Universiteit Delft	The Netherlands
Luca	Selmi	Universita degli Studi di Udine	Italy
Abhronil	Sengupta	Penn State University	United States
Junji	Senzaki	NAIST	Japan
Jung Hun	Seo	University at Buffalo	United States
Hyejeong	Seong	Korea Institute of Science and Technology	South Korea
Dong	Seup Lee	Texas Instruments	United States
Davood	Shahrjerdi	New York University	United States
Chong-Xin	Shan	Zhengzhou University	China
Dashan	Shang	Institute of Microelectronics of Chinese Academy of Sciences	China
Ravi	Shankar	STMicroelectronics Pte Ltd	Singapore
Tao	Shao	Chinese Academy of Sciences	China
Pankaj	Sharma	Micron Technology Inc.	United States
Harry	Shaw	NASA	United States
Mst Shamim Ara	Shawkat	Florida International University	United States
Shyh-Chiang	Shen	Georgia Institute of Technology	United States
Wenzhong	Shen	Shanghai Jiao Tong University	China
Xing	Sheng	Tsinghua University	China
Yanli	Shi	Yunnan University	China
Jia-Min	Shieh	National Nano Device Laboratories	Taiwan
Andy	Shih	École de Technologie Supérieure	Canada
Pao-Chuan	Shih	Massachusetts Institute of Technology	United States
Wonbo	Shim	Seoul National University of Science and Technology	South Korea
Takao	Shimizu	National Institute for Materials Science	Japan
Changhwan	Shin	Korea University	South Korea

First Name	Last Name	Affiliation	Country
Sanghoon	Shin	Intel Corporation	United States
Shoso	Shingubara	Kansai University	Japan
Keisuke	Shinohara	Teledyne Scientific & Imaging	United States
Mahmoud	Shousha	Wuerth Elektronik eiSos GmbH & Company KG	Germany
Mayank	Shrivastava	Indian Institute of Science	India
Shalini	Shrivastava	Indian Institute of Technology Bombay	India
Mengwei	Si	Shanghai Jiao Tong University	China
Moiz	Siddiqi	Metron Inc.	United States
Urmita	Sikder	University of California Berkeley	United States
Scott	Sills	Micron Technology Inc.	United States
Helena	Silva	University of Connecticut	United States
Luca	Silvestri	Synopsys Switzerland LLC	Switzerland
Eddy	Simoen	IMEC	Belgium
Jagar	Singh	GlobalFoundries Inc.	United States
Manikant	Singh	University of Bristol	United Kingdom
Ranveer	Singh	University of Wisconsin-Madison	United States
Shakti	Singh	Khalifa University	United Arab Emirates
Uttam	Singiseti	University at Buffalo	United States
Rajat	Sinha	GlobalFoundries Inc.	India
Henning	Sirringhaus	University of Cambridge	United Kingdom
Andrei	Slavin	Oakland University	United States
Stefan	Slesazek	NaMLab GmbH	Germany
Philippe	Smet	Ghent University	Belgium
Shahadat	Sohel	The Ohio State University	United States
Reza	Soleimanzadeh	École Polytechnique Fédérale de Lausanne	Switzerland
Kyung-Ah	Son	HRL Laboratories	United States
Aimin	Song	University of Manchester	United Kingdom
Cheng	Song	Tsinghua University	China
Jizhou	Song	Zhejiang University	China
Yi	Song	IBM	United States
Marko	Sonkki	Ericsson Antenna Technology Germany GmbH	Germany
Andrea	Spanu	University of Cagliari	Italy
James	Speck	University of California Santa Barbara	United States
Radim	Špetík	ON Semiconductor	Czech Republic
Radu	Sporea	University of Surrey	United Kingdom
Tathagata	Srimani	Massachusetts Institute of Technology	United States
Purushothaman	Srinivasan	GlobalFoundries Inc.	United States
Siwapon	Srisonphan	Kasetsart University	Thailand
Vishnu	Srivastava	CSIR-CEERI Pilani	India
Jan	Stake	Chalmers University of Technology	Sweden
Spyros	Stathopoulos	University of Southampton	United Kingdom
Stephan	Steinhauer	KTH Royal Institute of Technology	Sweden
Arno	Stockman	BelGaN	Belgium
Sebastiano	Strangio	Università degli Studi di Pisa	Italy
Pin	Su	National Chiao Tung University	Taiwan
Alexandre	Subirats	Micron Technology Inc.	United States
Arulkumaran	Subramaniam	Nanyang Technological University	Singapore
Akhil	Sudarasanan	Indian Institute of Technology Hyderabad	India
Tetsuya	Suemitsu	Tohoku University	Japan
Chang	Suh	Texas Instruments	United States
R. Scott	Summerfelt	Texas Instruments	United States
Qian	Sun	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Sheng	Sun	Peking University	China
Jordi	Sune	Universidad Autónoma de Barcelona	Spain
Hoon	Sung	Intel Corporation	United States

First Name	Last Name	Affiliation	Country
Woongje	Sung	State University of New York Polytechnic Institute	United States
Ateeq	Suria	Stanford University	United States
Teruo	Suzuki	Socionext Inc.	Japan
Viktor	Sverdlov	Technical University of Vienna	Austria
Victor V.	Sysoev	Yuri Gagarin State Technical University of Saratov	Russia
Pascal	't Hart	TU Delft	The Netherlands
Tomihisa	Tachibana	National Institute of Advanced Industrial Science and Technology	Japan
Ishibashi	Tadao	NTT	Italy
Marko	Tadger	Naval Research Laboratory	United States
Maher	Tahhan	Raytheon Technologies Corporation	United States
Huiling	Tai	University of Electronic Science and Technology of China	China
Ya Hsiang	Tai	National Chiao Tung University	Taiwan
Ketankumar	Tailor	Intel Foundation	United States
Kosuke	Takenaka	Osaka University	Japan
Kiyoshi	Takeuchi	The University of Tokyo	Japan
Srinivasa Reddy	Tamalampudi	New York University Abu Dhabi	United Arab Emirates
Shingo	Tamaru	National Institute of Advanced Industrial Science and Technology Tsukuba Center Tsukuba Central	Japan
Chih Shan	Tan	National Chiao Tung University	Taiwan
Aiwei	Tang	Beijing Jiaotong University	China
Jianshi	Tang	Tsinghua University	China
Tien-Hao	Tang	UMC	Taiwan
Wing Man	Tang	University of Hong Kong	Hong Kong
Xiaoyan	Tang	Xidian University	China
Zhikai	Tang	Efficient Power Conversion Corporation	United States
Lu-Qi	Tao	University of Science and Technology Beijing	China
Milan	Tapajna	Institute of Electrical Engineering SAS	Slovakia
Rabih	Tauk	Lebanese University Faculty of Science	Lebanon
Jeffrey	Teng	Georgia Institute of Technology	United States
Tomohide	Terashima	Mitsubishi Electric Corporation	Japan
Kornelius	Tetzner	Ferdinand-Braun-Institut Leibniz-Institut fur Hochstfrequenztechnik	Germany
Paragkumar	Thadesar	QUALCOMM Inc.	United States
Sudhakar Babu	Thanikanti	UNITEN	Malaysia
Aaron	Thean	National University of Singapore	Singapore
Han Wui	Then	Intel Corporation	United States
Christoforos	Theodorou	Grenoble INP	France
Fabian	Thome	Fraunhofer IAF	Germany
Muthiah	Thottappan	Indian Institute of Technology Varanasi	India
Manfred	Thumm	Karlsruhe Institute of Technology	Germany
He	Tian	Tsinghua University	China
Yonghui	Tian	Lanzhou University	China
David	Ting	Jet Propulsion Laboratory	United States
Pramod	Tiwari	Indian Institute of Technology Patna	India
Shree Prakash	Tiwari	Indian Institute of Technology Jodhpur	India
Katsuhiko	Tomioka	Hokkaido University	Japan
Roman	Torgashov	Russian Academy of Sciences	Russia
Akira	Toriumi	University of Tokyo	Japan
Nikolay	Torkhov	Tomsk State University of Control Systems and Radioelectronics	Russia
Vishal	Trivedi	Freescale Semiconductor Inc.	United States
Huynh-Bao	Trong	Taiwan Semiconductor Manufacturing Company Ltd	Canada
Feng-Yu	Tsai	National Taiwan University	Taiwan

First Name	Last Name	Affiliation	Country
Jung-Hui	Tsai	National Kaohsiung Normal University	Taiwan
Tsung-Ming	Tsai	National Sun Yat-sen University	Taiwan
Charalampos	Tsiouostas,	National Technical University of Athens	Greece
Toshiyuki	Tsuchiya	Kyoto University	Japan
Hiroshi	Tsuji	NHK Science and Technical Research Lab	Japan
Soichiro	Tsujino	Paul Scherrer Institut	Switzerland
Gen	Tsutsui	IBM	United States
Takuya	Tsutsumi	NTT Corporation	Japan
Christian	Tückmantel	University of Wuppertal	Germany
Ahmet	Tura	Intel Corporation	United States
Stanislav	Tyaginov	IMEC	Belgium
Wasi	Uddin	Indian Institute of Technology Delhi	India
Daisuke	Ueda	Kyoto Kogei Sen'i Daigaku	Japan
Tetsuzo	Ueda	Matsushita Electric Industrial Company Ltd	Japan
Tsutomu	Uesugi	Toyota Central R&D Labs., Inc.	Japan
Giacomo	Ulisse	Goethe-Universität Frankfurt am Main	Germany
Navnidhi	Upadhyay	University of Massachusetts Amherst	United States
Yukiharu	Uraoka	NAIST	Japan
Michael	Uren	University of Bristol	United Kingdom
Muhammad	Usman	KTH Royal Institute of Technology	Sweden
Muhammad	Usman	National Centre for Physics	Pakistan
Senthil	Vadakupudhu Palayam	IMEC	Belgium
Senthil Srinivasan	Vadakupudhu- Palayam	University of Stuttgart	Germany
Ilia	Valov	Forschungszentrum Jülich GmbH	Germany
Kees	Van Der Zouw	University of Twente	The Netherlands
William	Vandenbergh	University of Texas at Dallas	United States
Venkata Narayana Rao	Vanukuru	GlobalFoundries Inc.	United States
Enrico	Varesi	Micron Technology Inc.	Italy
Dhanooop	Varghese	Texas Instruments	United States
Vladislav	Vashchenko	Maxim Integrated	United States
Reinaldo	Vega	IBM	United States
Alin	Velea	Institutul National de Cercetare-Dezvoltare Pentru Fizica	Romania
Anabela	Veloso	IMEC	Belgium
Umamaheswara	Vemulapati	Hitachi ABB Power Grids	Switzerland
Claudio	Verona	Università di Roma "Tor Vergata"	Italy
Devin	Verreck	IMEC	Belgium
Andrei	Vescan	RWTH Aachen University	Germany
Vincenzo	Vinciguerra	STMicroelectronics	Switzerland
Alexander	Vlasov	Naval Research Laboratory	United States
Jan	Vobecky	Hitachi ABB Power Grids	Switzerland
Joachim	Vollbrecht	University of Postdam	Germany
Jan	Voves	Ceske Vysoke Ucení Technické v Praze	Czech Republic
Pratik	Vyas	The University of Texas at Dallas	United States
John	Wager	Oregon State University	United States
Sigurd	Wagner	Princeton University	United States
Muhammad A.	Wahab	Intel Corporation	United States
Changjin	Wan	Nanjing University	China
Jing	Wan	Fudan University	China
Qing	Wan	Nanjing University	China
Han	Wang	University of Southern California	United States
Hong	Wang	Xidian University	China
Huasheng	Wang	Soochow University	China

First Name	Last Name	Affiliation	Country
I-Ting	Wang	National Chiao Tung University	Taiwan
Jing	Wang	University of South Florida	United States
Lin	Wang	Shanghai Institute of Technical Physics CAS	China
Linzhi	Wang	Tianma Micro-Electronics Company Ltd	China
Maojun	Wang	Peking University	China
Mingxiang	Wang	Soochow University	China
Nan	Wang	Institute of Microelectronics, Agency for Science, Technology and Research	Singapore
Panni	Wang	Western Digital Corporation	United States
Ping	Wang	University of Michigan	United States
Renjie	Wang	McGill University	Canada
Ruidi	Wang	University of Electronic Science and Technology of China	China
Runsheng	Wang	Peking University	China
Sheng Kai	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Shui Jinn	Wang	National Cheng Kung University	Taiwan
Shujie	Wang	Henan University	China
Sui-Dong	Wang	Soochow University	China
Taifang	Wang	École Polytechnique Fédérale de Lausanne	Switzerland
Wei	Wang	Jilin University	China
Wei	Wang	Peng Cheng Laboratory	China
Xi	Wang	Xi'an University of Technology	China
Xiaolei	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Xiaomu	Wang	Nanjing University	China
Xingsheng	Wang	Huazhong University of Science and Technology	China
Xinhua	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Xinwei	Wang	Peking University Shenzhen Graduate School	China
Yijiao	Wang	Beihang University	China
Yiming	Wang	Shandong University	China
Yue	Wang	Xi'an Jiaotong University	China
Zheng	Wang	Georgia Institute of Technology	United States
Zhenxing	Wang	National Center for Nanoscience and Nanotechnology	China
Zhiguang	Wang	Xi'an Jiaotong University	China
Zhongqiang	Wang	Northeast Normal University	China
Zhongrui	Wang	University of Hong Kong	Hong Kong
Zongwei	Wang	Peking University	China
Atom	Watanabe	IBM	United States
Justin	Weber	Intel Corporation	United States
Jin	Wei	Hong Kong University of Science and Technology	Hong Kong
Jin	Wei	Peking University	China
Xianlong	Wei	Peking university	China
Zhanhua	Wei	Huaqiao University	China
Nils	Weimann	University of Duisburg-Essen	Germany
Martin	Weis	Slovak University of Technology	Slovakia
Dennis	Weller	Karlsruher Institut für Technologie	Germany
Deqi	Wen	Michigan State University	United States
Christian	Wenger	IHP Microelectronics GmbH	Germany
Lars-Erik	Wernersson	Lund University	Sweden
Christian	Wetzel	Rensselaer Polytechnic Institute	United States
Jonathan	Wierer	Lehigh University	United States
Nicholas	Williams	Northwestern University	United States
Madison	Wilson	University of California San Diego	United States
Hui-Yung	Wong	San Jose State University	United States

First Name	Last Name	Affiliation	Country
Joel	Wong	HRL Laboratories	United States
Man	Wong	The Hong Kong University of Science and Technology	Hong Kong
Man Hoi	Wong	University of Massachusetts Lowell	United States
Matthew	Wong	UC Santa Barbara	United States
William	Wong	University of Waterloo	Canada
Jiyong	Woo	Kyungpook National University	South Korea
John	Wrbanek	NASA John H Glenn Research Center	United States
Chao-Hsin	Wu	National Taiwan University	Taiwan
Di	Wu	Hefei University of Technology	China
Ernest	Wu	IBM	United States
Heng	Wu	IBM	United States
Huaqiang	Wu	Tsinghua University	China
Jiang	Wu	University of Electronic Science and Technology of China	China
Ke	Wu	Polytechnique Montreal	Canada
Peng	Wu	MIT	United States
Ping	Wu	Northwest Institute of Nuclear Technology	China
Shin-Tson	Wu	University of Central Florida	United States
Tian-Li	Wu	National Yang Ming Chiao Tung University	Taiwan
Wei	Wu	University of Southern California	United States
Wei-Jing	Wu	Institute of Polymer Optoelectronic Materials and Devices	China
Xiaohan	Wu	Fudan University	China
Yang	Wu	China Academy of Engineering Physics Institute of Applied Electronics	China
Yifeng	Wu	Transphorm Inc.	United States
Yuh-Renn	Wu	National Taiwan University	Taiwan
Yung-Chun	Wu	National Tsing Hua University	Taiwan
Yung-Hsien	Wu	National Tsing-Hua University	Taiwan
George	Xereas	McGill University	Canada
Yue	Xi	Tsinghua University School of Integrated Circuits	China
Yidong	Xia	Nanjing University	China
Zhanbo	Xia	Ohio State University	United States
Minghan	Xian	Micron Technology Inc.	United States
Yang	Xiang	IMEC	Belgium
Ming	Xiao	Virginia Polytechnic Institute and State University	United States
T. Patrick	Xiao	Sandia National Laboratory	United States
Wenwu	Xiao	Xiangtan University	China
Chao	Xie	Anhui University	China
Huikai	Xie	Beijing Institute of Technology	China
Jin	Xie	Zhejiang University	China
Sihan	Xie	Massachusetts Institute of Technology	United States
Wenfa	Xie	Jilin University	China
Feng	Xu	Tsinghua University	China
Guangwei	Xu	University of Science and Technology of China	China
Guangyu	Xu	University of Massachusetts Amherst	United States
Hongya	Xu	Lanzhou University	China
Nuo	Xu	University of California Berkeley	United States
Xiaobao	Xu	Nanjing University of Science and Technology	China
Xiaopeng	Xu	Synopsys Inc.	United States
Xiaoxin	Xu	Institute of Microelectronics of Chinese Academy of Sciences	China
Yang	Xu	Zhejiang University	China
Yuehang	Xu	University of Electronic Science and Technology of China	China
Jin	Xue	Massachusetts Institute of Technology	United States

First Name	Last Name	Affiliation	Country
Kan-Hao	Xue	Huazhong University of Science and Technology	China
Xiaoyong	Xue	Fudan University	China
Chandan	Yadav	National Institute of Technology Calicut	India
Manoj	Yadav	POSTECH MSE	South Korea
Sachin	Yadav	IMEC	Belgium
Eilam	Yalon	Technion—Israel Institute of Technology	Israel
Yuusuke	Yamaguchi	University of Fukui	Japan
Keisuke	Yamamoto	Kyushu University	Japan
Xingbin	Yan	Male Doctoral Supervisor Lanzhou Institute of Chemical Physics	China
Yan	Yan	Shenzhen University	China
Yang	Yan	University of Electronic Science and Technology of China	China
Chia-Ming	Yang	Chang Gung University	Taiwan
Chih Chung	Yang	National Taiwan University	Taiwan
Huan	Yang	Peking University Shenzhen Graduate School	China
Joshua	Yang	Viterbo College	United States
Ling	Yang	Xidian University	China
Shu	Yang	Zhejiang University	China
Tsung-Han	Yang	Arizona State University	United States
Weiqing	Yang	Southwest Jiaotong University	China
Xiangyu	Yang	Micron Technology Inc.	United States
Yang	Yang	University of Technology Sydney	Australia
Yansong	Yang	The Hong Kong University of Science and Technology	Hong Kong
Yuchao	Yang	Peking University	China
Peng	Yao	Tsinghua University Institute of Microelectronics	China
Yao	Yao	Chengdu University of Information Technology	China
Yixu	Yao	Chinese Academy of Sciences	China
Elahe	Yarmoghaddam	New York University Tandon School of Engineering	United States
Jiandong	Ye	Nanjing University	China
Peide	Ye	Purdue University	United States
Zhou	Ye	Shenzhen University	China
Ping-Hung	Yeh	Tamkang University	Taiwan
Teng-Hao	Yeh	Macronix International Company, Ltd.	Taiwan
Wei-Chang	Yeh	National Tsing Hua University	Taiwan
Bo	Yi	University of Electronic Science and Technology of China	China
Yong	Yin	University of Electronic Science and Technology of China	China
Hanbin	Ying	Georgia Institute of Technology	United States
Geonwook	Yoo	Soongsil University	South Korea
Hocheon	Yoo	Gachon University	South Korea
Sungmin	Yoon	Kyung Hee University	South Korea
Youngki	Yoon	University of Waterloo	Canada
Long	You	Huazhong University of Science and Technology	China
Sheng-Joue	Young	National United University	United States
Hao	Yu	IMEC	Belgium
Hongbin	Yu	Arizona State University	United States
Hsin-Chieh	Yu	National Yang Ming Chiao Tung University	Taiwan
Hyun-Yong	Yu	Korea University	South Korea
Xiao	Yu	Zhejiang University	China
Yongqiang	Yu	Hefei University of Technology	China
Feng	Yun	Xi'an Jiaotong University	China
Sabahattin	Yurt	QUALCOMM Inc.	United States
Shaw	Zachary	Texas Tech University	United States
Nicolò	Zagni	University of Modena and Reggio Emilia	Italy

First Name	Last Name	Affiliation	Country
Houman	Zahedmanesh	IMEC	Belgium
Cristian	Zambelli	University of Ferrara	Italy
Zhigang	Zang	Chongqing University	China
Enrico	Zanoni	Università degli Studi di Padova	Italy
Tommaso	Zanotti	Università degli Studi di Modena e Reggio Emilia	Italy
Alexander	Zaslavsky	Brown University	United States
Valentina	Zega	Polytechnic University of Milan	Italy
Fei	Zeng	Tsinghua University	China
Ke	Zeng	University at Buffalo	United States
Lang	Zeng	Beihang University	China
Longhui	Zeng	University of California San Diego	United States
Yuping	Zeng	University of Delaware	United States
Carl-Mikael	Zetterling	KTH Royal Institute of Technology	Sweden
Yiqiang	Zhan	Fudan University	China
Chen	Zhang	IBM	United States
Dongzhi	Zhang	China University of Petroleum	China
Fujun	Zhang	Institute of Optoelectronic Technology	China
Han	Zhang	Shenzhen University	China
Huilong	Zhang	University of Wisconsin-Madison	United States
Jian	Zhang	Liverpool John Moores University	United Kingdom
Jiawei	Zhang	Shandong University	China
Jinfeng	Zhang	Xidian University	China
Jun	Zhang	National University of Defense Technology	China
Lei	Zhang	Institute of Materials Research and Engineering	Singapore
Liang	Zhang	University of Strathclyde	United Kingdom
Lining	Zhang	Peking University	China
Lining	Zhang	Shenzhen University	China
Long	Zhang	Southeast University	China
Meng	Zhang	College of Electronic Science and Technology	China
Min	Zhang	Peking University Shenzhen Graduate School	China
Qi	Zhang	Huazhong University of Science and Technology	China
Qichun	Zhang	City University of Hong Kong	Hong Kong
Rui	Zhang	Zhejiang University	China
Ruifeng	Zhang	University of Electronic Science and Technology of China	China
Shengdong	Zhang	Peking University	China
Shuye	Zhang	Harbin Institute of Technology	United States
Wei	Zhang	Liverpool John Moores University	United Kingdom
Wentong	Zhang	University of Electronic Science and Technology of China	China
Xiaodong	Zhang	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Xuchen	Zhang	Georgia Institute of Technology	United States
Yachao	Zhang	Xidian University	China
Yide	Zhang	California Institute of Technology	United States
Yong	Zhang	University of Electronic Science and Technology of China	China
Yue	Zhang	Beihang University	China
Yuhao	Zhang	Virginia Tech	United States
Bo	Zhao	Stanford University	United States
Chun	Zhao	Xi'an Jiaotong-Liverpool University	China
Dewei	Zhao	Sichuan University	China
Feng	Zhao	Washington State University	United States
Liang	Zhao	Zhejiang University	China
Ming	Zhao	IMEC	Belgium
Qing-Tai	Zhao	Forschungszentrum Julich GmbH	Germany
Weisheng	Zhao	Beihang University	China

First Name	Last Name	Affiliation	Country
Xiaojin	Zhao	Shenzhen University	China
You	Zhao	Xi'an Jiaotong University	China
Yuda	Zhao	Zhejiang University	China
Huai	Zheng	Wuhan University	China
Jun	Zheng	Institute of Semiconductors Chinese Academy of Sciences	China
Qiwen	Zheng	Chinese Academy of Sciences	China
Xiao-Hong	Zheng	Institute of Solid State Physics Chinese Academy of Sciences	China
Xuejun	Zheng	Xiangtan University	China
Zheyang	Zheng	Hong Kong University of Science and Technology	Hong Kong
Haizheng	Zhong	Beijing Institute of Technology	China
Sihua	Zhong	Jiangsu Ocean University	China
Changjian	Zhou	South China University of Technology	China
Fan	Zhou	Apple Inc.	United States
Hang	Zhou	Peking University	China
Hong	Zhou	Xidian University	China
Peng	Zhou	Fudan University	China
Qi	Zhou	University of Electronic Science and Technology of China	China
Qifa	Zhou	University of Southern California	United States
Wei	Zhou	Hong Kong University of Science and Technology	Hong Kong
Xianda	Zhou	Sun Yat-sen University	China
Ye	Zhou	Shenzhen University	China
Fu Rong	Zhu	Hong Kong Baptist University	Hong Kong
Hui	Zhu	Beijing University of Technology	China
Huilong	Zhu	Institute of Microelectronics of Chinese Academy of Sciences	China
Jiadi	Zhu	Massachusetts Institute of Technology	United States
Jiejie	Zhu	Xidian University	China
Li Qiang	Zhu	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Min	Zhu	Shanghai Institute of Micro-System and Information Technology	China
Mingda	Zhu	Finisar Corporation	United States
Yao	Zhu	Institute of Microelectronics, Agency for Science, Technology and Research	Singapore
Fei	Zhuge	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Fuwei	Zhuge	Huazhong University of Science and Technology	China
Serge	Zhuiykov	Ghent University	Belgium
Cheng	Zhuo	Zhejiang University	China
Martin	Ziegler	Technische Universitat Ilmenau	Germany
Thomas	Zimmer	Université de Bordeaux	France
Lars	Zimmermann	IHP Microelectronics	Germany
Cezar	Zota	IBM	Switzerland
Xinbo	Zou	ShanghaiTech University	China
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Tarun	Agrawal	ETH Zurich	Switzerland
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Samuel	Bader	Cornell University	United States
Ghadeer	Badran	University of Huddersfield	United Kingdom

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Byung Seong	Bae	Hoseo University	South Korea
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Jong-Uk	Bae	LG Display	South Korea
Chang-Ki	Baek	POSTECH	South Korea
Rock-Hyun	Baek	POSTECH MSE	South Korea
Seung-Heon	Baek	Korea Institute of Science and Technology	South Korea
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Writam	Banerjee	Pohang University of Science and Technology	South Korea
Wenzhong	Bao	Fudan University	China
Xinyu	Bao	TSMC Ltd	Taiwan
Hugh	Barnaby	Arizona State University	United States
Pedro	Barquinha	Universidade Nova de Lisboa FCT	Portugal
Michael	Basler	Fraunhofer Institute for Applied Solid State Physics IAF	Germany
Thomas	Basler	Technische Universität Chemnitz	Germany
Rupa	Basu	Lancaster University	United Kingdom
Joan	Bausells	Centro Nacional de Microelectronica	Spain
Mehdi	Bazizi	Applied Materials Inc.	United States
Arnout	Beckers	IMEC	Belgium
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Federico	Bella	Politecnico di Torino	Italy
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Simon	Bleiker	KTH Royal Institute of Technology	Sweden
Boni	Boksteen	Hitachi ABB Power Grids	Switzerland
William	Borders	National Institute of Standards and Technology	United States
Matteo	Borga	IMEC	Belgium
Buddha Deka	Boruah	University of Cambridge	United Kingdom
Arijit	Bose	Nagoya Institute of Technology	Japan
Gianluca	Boselli	Texas Instruments	United States
Panagiotis	Bousoulas	National Technical University of Athens	Greece
Chris	Bowen	University of Bath	United Kingdom
Rita	Branquinho	Universidade Nova de Lisboa	Portugal
Laurent	Breuil	IMEC	Belgium
David	Brown	BAE Systems Inc.	United States
Liliana	Buda-Prejbanu	CEA	France
Fabian	Bufler	IMEC	Belgium
Erik	Bury	IMEC	Belgium

First Name	Last Name	Affiliation	Country
Fuxi	Cai	Applied Materials Inc.	United States
Kaiming	Cai	IMEC	Belgium
Yimao	Cai	Peking University	China
Yong	Cai	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Cinzia	Caliendo	Istituto di Fotonica e Nanotecnologie (IFN-CNR)	Italy
Humberto	Campanella	Skyworks Solut	Singapore
Joe C.	Campbell	University of Virginia	United States
Kristy	Campbell	Boise State University	United States
Jesus	Cañas	Institut Néel	France
Giuseppe	Cantarella	Libera Università di Bolzano Facoltà di Scienze e Tecnologie	Italy
Kurtis	Cantley	Boise State University	United States
Hongtao	Cao	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Qing	Cao	University of Illinois at Urbana-Champaign	United States
Yibing	Cao	Northwest Institute of Nuclear Technology	China
Yu	Cao	Qorvo	United States
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Greg	Carman	University of California Los Angeles	United States
Hamilton	Carrillo Nunez	Aix-Marseille University	France
Alexandre	Carvalho	Universidade de Aveiro	Portugal
Mikael	Casse	CEA Grenoble	France
Marco	Cassinero	Politecnico di Milano	Italy
Niccolo'	Castellani	University Grenoble Alpes and CEA	France
Federica	Catania	Free University of Bozen-Bolzano	Italy
Umberto	Celano	IMEC	Belgium
Lorenzo	Cerati	STMicroelectronics SRL Sede di Agrate Brianza	Italy
Antonio	Cerdeira	CINVESTAV	Mexico
Ho-Young	Cha	Hongik University	South Korea
Kelson	Chabak	Air Force Research Laboratory	United States
Yang	Chai	Hong Kong Polytechnic University	Hong Kong
Zheng	Chai	Xi'an Jiaotong University	China
Paddy	Chan	University of Hong Kong	Hong Kong
Edward Yi	Chang	National Chiao Tung University	Taiwan
Jingjing	Chang	Xidian University	China
Jiwon	Chang	Yonsei University	South Korea
Josephine	Chang	Northrop Grumman Electronic Systems	United States
Kuan-Chang	Chang	Peking University	China
Sheng-Po	Chang	National Cheng Kung University	Taiwan
Sou-Chi	Chang	Georgia Institute of Technology	United States
Ting-Chang	Chang	National Sun Yat-sen University	Taiwan
Tzu-Hsuan	Chang	National Taiwan University	Taiwan
Wen Hsin	Chang	National Institute of Advanced Industrial Science and Technology	Japan
Kuei-Shu	Chang-Liao	National Tsing Hua University	Taiwan
Adrian	Chasin	IMEC	Belgium
Dibyendu	Chatterjee	Indian Institute of Technology Bombay	India
Reet	Chaudhuri	Cornell University	United States
Sandeep	Chaudhuri	University of South Carolina	United States
Yogesh	Chauhan	Indian Institute of Technology Kanpur	India
Wenjie	Che	New Mexico State University	United States
Nikolay G.	Chechenin	Lomonosov Moscow State University	Russia
Baile	Chen	Shanghai Tech University	China
Bing	Chen	Zhejiang University	China
Chaoping	Chen	Shanghai Jiao Tong University	United States

First Name	Last Name	Affiliation	Country
Chin-Yi	Chen	Purdue University	United States
Di	Chen	Shanghai Jiao Tong University	China
Dunjun	Chen	Nanjing University	China
Edward	Chen	TSMC	Taiwan
Fan	Chen	Samsung	United States
Haibao	Chen	Shanghai Jiao Tong University	China
Jen-Sue	Chen	National Cheng Kung University	Taiwan
Jianxin	Chen	Chinese Academy of Sciences	China
Jiezhi	Chen	Shandong University	China
Jun	Chen	Sun Yat-sen University	China
Junren	Chen	Institute of Neuroinformatics	Switzerland
Kevin	Chen	Hong Kong University of Science and Technology	Hong Kong
Kuan-Neng	Chen	National Chiao Tung University	Taiwan
Lin	Chen	Fudan University	China
Lingen	Chen	Naval University of Engineering	China
Miin-Jang	Chen	National Taiwan University	Taiwan
Rongsheng	Chen	Hong Kong University of Science and Technology	Hong Kong
Rongsheng	Chen	South China University of Technology	China
Shih-Hung	Chen	IMEC	Belgium
Shuming	Chen	Southern University of Science and Technology	China
Teng-Ming	Chen	National Yang Ming Chiao Tung University	Taiwan
Wei-Chen	Chen	Macronix International Company, Ltd	Taiwan
Wei-Chen	Chen	Stanford University	United States
Weize	Chen	ON Semiconductor	United States
Xiaojie	Chen	Sichuan University	China
Yangyin	Chen	IMEC	Belgium
Yangyin	Chen	Western Digital Technologies Inc.	United States
Ying-Chen	Chen	Northern Arizona University	United States
Zhizhong	Chen	Peking University	China
Zhong	Chen	University of Arkansas	United States
Binjie	Cheng	Synopsys Inc.	United Kingdom
Buwen	Cheng	Institute of Semiconductors Chinese Academy of Sciences	China
Chun-Hu	Cheng	National Taiwan Normal University	Taiwan
I-Chun	Cheng	National Taiwan University	Taiwan
Kangguo	Cheng	IBM	United States
Ran	Cheng	Zhejiang University	China
Zhihui	Cheng	Duke University	United States
Igor	Chernyavskiy	Naval Research Laboratory	United States
Hung-Li	Chiang	Taiwan Semiconductor Manufacturing Company Ltd	Taiwan
Meng-Hsueh	Chiang	National Cheng Kung University	Taiwan
Chao-Hsin	Chien	National Chiao Tung University	Taiwan
Wei-Chih	Chien	Macronix International Company, Ltd.	Taiwan
Alessandro	Chini	University of Modena and Reggio Emilia	Italy
Hsien-Chin	Chiu	Chang Gung University	Taiwan
Sung Haeng	Cho	Electronics and Telecommunication Research Institute	South Korea
Seongjae	Cho	Gachon University	South Korea
Won-Ju	Cho	Kwangwoon University	South Korea
Vamsy	Chodavarapu	University of Chodacarapu	United States
Gihun	Choe	Georgia Institute of Technology College of Engineering	United States
Eunmi	Choi	Ulsan National Institute of Science and Technology	South Korea
Hyejeong	Choi	Yonsei University	South Korea
Rino	Choi	Inha University	South Korea
Sungju	Choi	Kookmin University	South Korea
Chi Wei	Chow	National Yang Ming Chiao Tung University	Hong Kong

First Name	Last Name	Affiliation	Country
Nadim	Chowdhury	Massachusetts Institute of Technology	United States
Srabanti	Chowdhury	Stanford University	United States
Philippe	Christol	University of Montpellier	France
Alexander	Chronos	Imperial College	United Kingdom
Dewei	Chu	University of New South Wales	Australia
Rongming	Chu	Penn State University	United States
Ta-Ya	Chu	National Research Council, Canada	Canada
Kai-Hsin	Chuang	PUFsecurity Inc.	Taiwan
Eduardo	Chumbes	Raytheon Integrated Defense Systems	United States
Chin-Han	Chung	National Chiao Tung University	Taiwan
Roy	Chung	Kyungpook National University	South Korea
Robert	Coffie	RLC Solutions	United States
Oleg	Cojocari	ACST GmbH	Germany
Daniel	Connelly	University of California at Berkeley	United States
Brian	Corbett	Tyndall National Institute	Ireland
Thibault	Cosnier	IMEC	Belgium
Piero	Cosseddu	University of Cagliari	Italy
Angela	Coves	Universidad Miguel Hernández de Elche	Spain
Erika	Covi	NaMLab gGmbH	Germany
Tobias	Cramer	University of Bologna	Italy
Bogdan	Cretu	ENSICAEN	France
Bennett	Cromer	Cornell University	United States
Giovanni	Crupi	University of Messina	Italy
Edoardo	Cuniberto	New York University	United States
Maciej	Cwiklinski	Rohde und Schwarz GmbH und Company KG	Germany
Chetan	Dabhi	University of California Berkeley	United States
Gilles	Dambrine	IEMN	France
Bhaskar	Das	Indian Institute of Technology Bombay	India
Sanghamitra	Das	Silicon Institute of Technology	India
Suman	Das	Sikkim Manipal Institute of Technology	India
Avirup	Dasgupta	Indian Institute of Technology Roorkee	India
Sudeb	Dasgupta	Indian Institute of Technology Roorkee	India
Subrata	Datta	Microwave Tube Research & Development Centre	India
John	David	The University of Sheffield	United Kingdom
Sourav	De	Fraunhofer IPMS—Center Nanoelectronic Technologies CNT	Germany
Raffaele	De Rose	Universita degli Studi della Calabria	Italy
Michelly	De Souza	Centro Universitario da FEI	Brazil
Punyashloka	Debashis	Purdue University	United States
Corentin	Delacour	LIRMM	France
Quentin	Delhaye	Université Libre de Bruxelles École polytechnique de Bruxelles	Belgium
Nicholas	Dellas	Infineon Austria	Austria
Wanling	Deng	College of Information Science and Technology	China
Zhen	Deng	Institute of Physics Chinese Academy of Sciences	China
Dan	Denninghoff	Teledyne Scientific & Imaging	United States
Riccardo	Depetro	STMicroelectronics SRL Sede di Agrate Brianza	Italy
Sanchit	Deshmukh	Stanford University	United States
Veeresh	Deshpande	Helmholtz-Zentrum Berlin für Materialien und Energie GmbH	Germany
Jonas	Deuermeier	New University of Lisbon Faculty of Science and Technology	Portugal
Wouter	Devulder	IMEC	Belgium
Sarit	Dhar	Auburn University	United States
Mahmoud	Dhimish	University of Huddersfield	United Kingdom
Daryoosh	Dideban	University of Kashan	Iran

First Name	Last Name	Affiliation	Country
Charalabos	Dimitriadis	Aristotle University of Thessaloniki	Greece
Jinjun	Ding	Colorado State University	United States
Shi-Jin	Ding	Fudan University	China
Xukai	Ding	Southeast University	China
Thanh Viet	Dinh	NXP Semiconductors Belgium	Belgium
José	Diniz	Universidade Estadual de Campinas, Brazil	Brazil
Guillaume	Dion	Université de Sherbrooke	Canada
Nazareno	Donato	University of Cambridge	United Kingdom
Chengyuan	Dong	Shanghai Jiao Tong University	China
Shurong	Dong	Zhejiang University	China
Shuxiang	Dong	Peking University	China
Gerben	Doornbos	TSMC	Belgium
Rodrigo	Doria	Centro Universitario da FEI	Brazil
Behnoush	Dousti	The University of Texas at Dallas	United States
Karen	Dowling	Lawrence Livermore National Laboratory	United States
Francesco	Driussi	Universita degli Studi di Udine	Italy
Chao	Du	University of Michigan	United States
Chao-Hai	Du	Peking University	China
Baoxing	Duan	Xidian University	China
Meng	Duan	Synopsys Inc.	United Kingdom
Zhaoyun	Duan	University of Electronic Science and Technology of China	China
Alexander	Dubinov	RFNC-VNIIEF	Russia
Jean-Yves	Duboz	CRHEA	France
Ray	Duffy	Tyndall National Institute	Ireland
Stefan	Dünkel	GlobalFoundries Dresden Module One LLC & Company KG	Germany
Gourab	Dutta	Indian Institute of Technology Kharagpur	India
Charvaka	Duvvury	ESD Consultant	United States
Ursula	Ebels	CNRS-CEA Spintec	France
Abasifreke	Ebong	The University of North Carolina at Charlotte	United States
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Xin	Fan	University of Denver	United States
Zhiqiang	Fan	Northwest Institute of Nuclear Technology	China
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Xiaosheng	Fang	Fudan University	China
Matteo	Farronato	Polytechnic University of Milan	Italy
Patrick	Fay	University of Notre Dame	United States
Alexey	Fedotov	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Maximilian	Feil	Infineon Technologies AG	Germany

First Name	Last Name	Affiliation	Country
Jinjun	Feng	Beijing Vacuum Electronics Research Institute	China
Peijie	Feng	QUALCOMM Inc.	United States
Philip	Feng	University of Florida	United States
Claudio	Fiegna	University of Bologna	Italy
Ignasi	Fina	ICMAB	Spain
Patrick	Fiorenza	Consiglio Nazionale delle Ricerche	Italy
Massimo	Fischetti	University of Texas at Dallas	United States
Dan	Fleetwood	Vanderbilt University	United States
Andrew	Flewitt	University of Cambridge	United Kingdom
Karine	Florent	Micron Technology Inc.	United States
Xuanyao	Fong	National University of Singapore	Singapore
Stephen	Forrest	University of Michigan	United States
Ioannis	Fragkos	Lehigh University	United States
Anthony	Francis	Ozark Integrated Circuits, Inc.	United States
Jacopo	Franco	IMEC	Belgium
Aaron	Franklin	Duke University	United States
Sebastien	Fregonese	CNRS	France
Pavel	Freundlich	ON Semiconductor	United States
Martin	Frey	Synopsys Switzerland LLC	Switzerland
Peter	Friedrichs	Infineon Technologies AG	Germany
Kai	Fu	Arizona State University	United States
Wenjie	Fu	University of Electronic Science and Technology of China	China
Mami	Fujii	Nara Institute of Science and Technology	Japan
Shosuke	Fujii	Kioxia Corporation	Japan
Masahisa	Fujino	National Institute of Advanced Industrial Science	Japan
Naoto	Fujishima	Fuji Electric	Germany
Mamoru	Furuta	Kochi University of Technology	Japan
Alexander	Gabourie	Stanford University School of Engineering	United States
Anatoly	Galdetskiy	FSUE Istok	Russia
Vincent	Gambin	Northrup-Grumman Corporation	United States
Francisco	Gamiz	Universidad de Granada	Spain
Diana	Gamzina	SLAC National Accelerator Laboratory	United States
Ning	Gan	Ningbo University	China
Pratisha	Gangwar	Indian Institute of Technology Bombay	India
Bin	Gao	Tsinghua University	China
Daniele	Garbin	IMEC	Belgium
Francisco	Garcia-Sanchez	Simon Bolivar University	Venezuela
Kevin	Garello	SPINTEC	France
Xavier	Garros	CEA Grenoble	France
Lixin	Ge	QUALCOMM Inc.	United States
Michael	Geis	Massachusetts Institute of Technology	United States
Dimitra	Georgiadou	University of Southampton	United Kingdom
Gérard	Ghibaudo	IMEP-LAHC	France
Saugata	Ghose	University of Illinois Urbana-Champaign	United States
Bablu Kumar	Ghosh	Universiti Malaysia Sabah	Malaysia
Sanjay	Ghosh	Central Electronics Engineering Research Institute	India
Filippo	Giannazzo	CNR-IMM	Italy
Naum	Ginzburg	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Mikhail	Glyavin	Institute of Applied Physics of the Russian Academy of Sciences	Russia
Michele	Goano	Politecnico di Torino	Italy
Akira	Goda	Micron Technology Inc.	United States
Vincent	Goiffon	ISAE-SUPAERO	France
Vikrant	Gokhale	US Naval Research Laboratory	United States

First Name	Last Name	Affiliation	Country
Ali	Gokirmak	University of Connecticut	United States
Tayfun	Gokmen	IBM	United States
Prafful	Golani	University of Minnesota	United States
Henrique	Gomes	Univerity of the Algarve	Portugal
Roberto	Gomez-Garcia	Universidad de Alcala	Spain
Huarong	Gong	University of Electronic Science and Technology of China	China
Jiarui	Gong	University of Wisconsin-Madison	United States
Nanbo	Gong	Yale University	United States
Xiao	Gong	National University of Singapore	Singapore
Yubin	Gong	University of Electronic Science and Technology of China	China
Sujan K.	Gonugondla	Amazon.com	United States
Tomas	Gonzalez	Universidad de Salamanca	Spain
Yago	Gonzalez-Velo	Arizona State University	United States
Rupam	Goswami	KIIT University	India
Tibor	Grasser	TU Wien	Austria
Giuseppe	Greco	CNR-IMM	Italy
Andrew	Green	Air Force Research Laboratory Sensors Directorate	United States
Marty	Gregg	Queen's University Belfast	United Kingdom
Alexander	Grill	IMEC	Belgium
Vytautas	Grivickas	Vilnius University	Lithuania
Alessandro	Grossi	Infineon Technologies Italia S.r.l.	Italy
Timothy	Grotjohn	Michigan State University	United States
Shulin	Gu	Nanjing University	China
Yuandong	Gu	Shanghai University	China
Ximeng	Guan	IBM	United States
Jon Tomas	Gudmundsson	University of Iceland	Iceland
Diego	Guerra	Arizona State University	United States
Tue	Gunst	Synopsys Inc.	United States
Jing	Guo	University of Florida	United States
Liu	Guo	University of Electronic Science and Technology of China	China
Xiaojun	Guo	Shanghai Jiao Tong University	China
Yufeng	Guo	Nanjing University of Posts and Telecommunications	China
Chetan	Gupta	Indian Institute of Technology Kanpur	India
Chirag	Gupta	University of Wisconsin-Madison	United States
Geetak	Gupta	Transphorm Inc.	United States
Sumeet	Gupta	The Pennsylvania State University	United States
Edmundo	Gutiérrez-D.	Instituto Nacional de Astrofisica	Mexico
Marek	Guziewicz	Łukasiewicz Research Network—Institute of Microelectronic and Photonics	Poland
Romain	Gwozdiecki	CEA-LITEN	France
Daniel	Habersat	US Army Research Laboratory	United States
Anders	Hallén	KTH Royal Institute of Technology	Sweden
Hamida	Hallil	University of Bordeaux	France
Dedong	Han	Peking University	China
Genquan	Han	Xidian University	China
Jin-Woo	Han	Samsung Electronics	South Korea
Kijeong	Han	Wolfspeed	United States
Sang-Woo	Han	Penn State University	United States
Seong-Tae	Han	Korea Electrotechnology Research Institute	South Korea
Su-Ting	Han	Shenzhen University	China
Tae-Hee	Han	Hanyang University	United States
Tao	Han	Shanghai Jiao Tong University	China
Xiaotao	Han	Huazhong University of Science and Technology	China

First Name	Last Name	Affiliation	Country
Paul	Haney	NIST Center for Nanoscale Science and Technology	United States
Yue	Hao	Xidian University	China
Kenji	Hara	Hitachi Ltd.	Japan
Matthew	Hartensveld	Rochester Institute of Technology	United States
Pouya	Hashemi	IBM	United States
Naimul	Hassan	University of Texas at Dallas	United States
Ryoma	Hayakawa	National Institute for Materials Science	Japan
Pavel	Hazdra	Czech Technical University in Prague	Czech Republic
Gang	He	Anhui University	China
Hongyu	He	Yangtze University	China
Yu-Hui	He	Huazhong University of Science and Technology	China
Chris	Heidelberg	MIT	United States
Erik	Heijne	CERN	Switzerland
Markus	Hellenbrand	Lund University	Sweden
Henning	Helmers	Fraunhofer Institute for Solar Energy Systems ISE	Germany
Robert	Henderson	University of Edinburgh	United Kingdom
Yeon-Cheol	Heo	Samsung	South Korea
Dinusha	Herath		
	Mudiyanselage	Iowa State University	United States
Sukreen Hana	Herman	Universiti Teknologi MARA	Malaysia
Lars	Heuken	Institut für Mikroelektronik Stuttgart (IMS-CHIPs)	Germany
Austin	Hickman	Cornell University	United States
Christofer	Hierold	ETH Zurich	Switzerland
Masataka	Higashiwaki	National Institute of Information and Communications Technology	Japan
Oliver	Hilt	FBH Berlin	Germany
Digh	Hisamoto	Hitachi Ltd.	Japan
Brad	Hoff	Air Force Research Laboratory	United States
Alexander	Hölke	X-FAB	Malaysia
Mark	Hollis	MIT	United States
Naoto	Horiguchi	IMEC	Belgium
Masahiro	Horita	Nagoya University	Japan
Ray-Hua	Hornng	National Chiao Tung University	Taiwan
Peter	Horoyski	Communications and Power Industries, CPI Canada	Canada
Brian	Hoskins	National Institute of Standards and Technology	United States
Hideo	Hosono	Tokyo Institute of Technology	Japan
Shuoben	Hou	II-VI (Kista)	Sweden
Tuo-Hung	Hou	National Yang Ming Chiao Tung University	Taiwan
Jan Van	Houdt	IMEC	United States
Fu	Houqiang	Iowa State University	United States
Robert	Howell	Northrop Grumman Electronic Systems	United States
Vincent K. S.	Hsiao	National Chi Nan University	Taiwan
Chia-Sheng	Hsu	Georgia Institute of Technology College of Engineering	United States
Po-Kai	Hsu	Georgia Institute of Technology	United States
Shawn	Hsu	National Tsing Hua University	Taiwan
Jie	Hu	NXP Semiconductors Austin Oak Hill	United States
Shiben	Hu	TCL China Star Optoelectronics Technology Company, Ltd	China
Vita	Hu	National Taiwan University	Taiwan
Xiaoer	Hu	University of California, Berkeley	United States
Yuanyuan	Hu	Hunan University	China
Mengyuan	Hua	Hong Kong University of Science and Technology	Hong Kong
Mengyuan	Hua	Southern University of Science and Technology	China
Qilin	Hua	Institute of Nanoenergy and Nanosystems Chinese Academy of Sciences	China
Alex	Huang	University of Texas at Austin	United States

First Name	Last Name	Affiliation	Country
Bohr-Ran	Huang	National Taiwan University of Science and Technology	Taiwan
Chih-Fang	Huang	National Tsing Hua University	Taiwan
Chun-Yuan	Huang	National Taitung University	Taiwan
Feng	Huang	Sun Yat-sen University	China
Jianjang	Huang	National Taiwan University	Taiwan
Jung-Jie	Huang	Dayeh University	Taiwan
Peng	Huang	Peking University	China
Qianqian	Huang	Peking University	China
Sen	Huang	Institute of Microelectronics of Chinese Academy of Sciences	China
Weixing	Huang	Chinese Academy of Sciences	China
Yong Mao	Huang	Xihua University	China
Yongan	Huang	Huazhong University of Science	China
Zhujun	Huang	New York University	United States
Boris	Hudec	National Chiao Tung University	Taiwan
Peter	Huggard	STFC Rutherford Appleton Laboratory	United Kingdom
Yung-Jr	Hung	National Sun Yat-sen University	Taiwan
Wenxing	Huo	The Institute of Physics, Chinese Academy of Sciences	China
Andrew	Hurrell	Precision Acoustics Ltd	United Kingdom
Louis	Hutin	CEA-Leti	France
Cheol Seong	Hwang	Seoul National University	South Korea
Hyunsang	Hwang	Pohang University of Science and Technology	South Korea
Daniele	Ielmini	Politecnico di Milano	Italy
Koichi	Iiyama	Kanazawa University	Japan
Keiji	Ikeda	Kioxia Corporation	Japan
Kiju	Im	Samsung Display Company Ltd	South Korea
Ki-Sik	Im	Kumoh National Institute of Technology	South Korea
Jean Anne	Incorvia	The University of Texas at Austin	United States
Eleftherios	Ioannidis	AMS OSRAM	Austria
Adrian Mihai	Ionescu	Swiss Federal Institute of Technology (EPFL)	Switzerland
Koichi	Ishida	Technische Universitaet Dresden	Germany
Kazunari	Ishimaru	Kioxia Corporation	Japan
Ahmad	Islam	Air Force Research Laboratory Materials and Manufacturing Directorate	United States
Raisul	Islam	Stanford University	United States
Noriyuki	Iwamuro	Tsukuba Daigaku	Japan
Ruchil	Jain	GlobalFoundries Inc.	Singapore
Vibhor	Jain	IBM	United States
Michael Paul	Jallorina	Nara Sentan Kagaku Gijutsu Daigakuin Daigaku Busshitsu Sosei Kagaku Kenkyuka	Japan
Alex	James	Digital University Kerala	India
Raj	Jana	JANA Research Initiative	United States
Jaewon	Jang	Kyungpook National University	South Korea
Jin	Jang	Kyung Hee University	South Korea
Deep	Jariwala	University of Pennsylvania	United States
Himani	Jawa	Indian Institute of Technology Bombay	India
John	Jelonnek	Karlsruhe Institute of Technology	Germany
Biswajit	Jena	VIT University	India
Kevin	Jensen	Naval Research Laboratory	United States
Jongwook	Jeon	Konkuk University	South Korea
Jae Kyeong	Jeong	Hanyang University	South Korea
Dong	Ji	Stanford University	United States
Zhigang	Ji	Shanghai Jiao Tong University	China
Renxu	Jia	Xidian University	China
Chao	Jiang	National Center for Nanoscience and Technology	China

First Name	Last Name	Affiliation	Country
Chen	Jiang	Tsinghua University	China
Hao	Jiang	Fudan University	China
Huaxing	Jiang	The Hong Kong University of Science and Technology	Hong Kong
Jie	Jiang	Central South University	China
Pei-Hsun	Jiang	National Taiwan Normal University	Taiwan
Qimeng	Jiang	Chinese Academy of Sciences	China
Sheng	Jiang	Northwestern Polytechnical University	China
Sheng	Jiang	University of Gothenburg	Sweden
Yu-Long	Jiang	Fudan University	China
Hailong	Jiao	Peking University Shenzhen Graduate School	China
Chengji	Jin	Institute of Industrial Science, The University of Tokyo	Japan
Jidong	Jin	Hanyang University—Education Research Industry Cluster at Ansan	South Korea
Lei	Jin	Institute of Microelectronics of Chinese Academy of Sciences	China
Seonghoon	Jin	Samsung Semiconductor Inc.	United States
Yizheng	Jin	Zhejiang University	China
Yufeng	Jin	Shenzhen Graduate School of Peking University	China
Sameer	Joglekar	Intel Corporation	United States
Jungwoo	Joh	Texas Instruments	United States
Rohit	John	ETH Zürich	Switzerland
David	Johnsson	Intel Mobile Communications	Germany
Chandan	Joishi	The Ohio State University	United States
Saumil	Joshi	Micron Technology Inc.	United States
Ravi	Joshi	Texas Tech University	United States
Jinchuan	Ju	National University of Defense Technology	China
Christoph	Jungemann	RWTH Aachen University	Germany
Pilin	Junsangsri	Wentworth Institute of Technology	United States
Ben	Kaczer	IMEC	Belgium
Bhagyalakshmi	Kakarla	ETH Zurich	Switzerland
Shoji	Kakio	Yamanashi Daigaku—Kofu Campus	Japan
Anisha	Kalra	Indian Institute of Science	India
Masakazu	Kanechika	Toyota Central Research and Development Labs., Inc.	Japan
Hyemin	Kang	Korea Institute of Energy Technology (KENTECH)	South Korea
Jinfeng	Kang	Peking University	China
Kuo-Hsing	Kao	National Cheng Kung University	Taiwan
Ming-Yen	Kao	University of California Berkeley	United States
Robert	Kaplar	Sandia National Labs	United States
Ilya	Karpov	Intel Corporation	United States
Victor	Karpov	University of Toledo	United States
Makoto	Kasu	Saga University	Japan
Ankit	Kaul	Georgia Institute of Technology College of Engineering	United States
Harsupreet	Kaur	University of Delhi	India
Jamil	Kawa	Synopsys Inc.	United States
Hiroshi	Kawarada	Waseda University	Japan
Suzuki	Kazuhiko	Hokkaido University of Science	Japan
John	Kennedy	National Isotope Centre	New Zealand
Ming-Dou	Ker	National Yang Ming Chiao Tung University	Taiwan
Vishal	Kesari	Microwave Tube Research & Development Centre	India
Dolar	Khachariya	North Carolina State University	United States
Wan	Khairul	Universiti Malaysia Terengganu	Malaysia
Ali	Khakifirooz	Intel Corporation	United States
Asif	Khan	Georgia Institute of Technology	United States
Asir Intisar	Khan	Stanford University	United States

First Name	Last Name	Affiliation	Country
Hassan	Khan	Lahore University of Management Sciences	Pakistan
Akif Aabrar	Khandker	University of Notre Dame	United States
Abhishek	Khanna	University of Notre Dame	United States
Michael	Khazhinsky	Silicon Labs	United States
Afreen	Khursheed	Maulana Azad National Institute of Technology	India
Asal	Kiazadeh	CENIMAT	Portugal
Choong-Ki	Kim	SK hynix Inc.	South Korea
Dae Hwan	Kim	Kookmin University	South Korea
Dae Yeon	Kim	The University of Texas at Dallas	United States
Deok-Kee	Kim	Sejong University	South Korea
Dong Myong	Kim	Kookmin University	South Korea
Garam	Kim	Myongji University—Natural Science Campus	South Korea
Hogyoung	Kim	Seoul National University of Science and Technology	South Korea
Hyun Jae	Kim	Yonsei University	South Korea
Hyungjin	Kim	Inha University	South Korea
Hyun-Seop	Kim	University of Bristol	United Kingdom
Jeonghoon	Kim	University of California San Diego	United States
Junghwan	Kim	Tokyo Institute of Technology	Japan
Myunggil	Kim	Sung Kyun Kwan University	South Korea
Sangbum	Kim	Seoul National Univeristy	South Korea
Sang-Hyeon	Kim	Korea Institute of Science and Technology	South Korea
Sang-Jae	Kim	Jeju National University	South Korea
Sangwan	Kim	Sogang University	South Korea
Sang-Woo	Kim	Sungkyunkwan University	South Korea
Seyoung	Kim	Pohang University of Science and Technology	South Korea
Tae-Hyeon	Kim	Seoul National University	South Korea
Yong-Sang	Kim	Sungkyunkwan University	South Korea
Yoon	Kim	University of Seoul	South Korea
Tsunenobu	Kimoto	Kyoto University	Japan
Kei	Kimura	Sony Group Corporation Atsugi Technology Center	Japan
Mutsumi	Kimura	Ryukoku University	Japan
Dmitry	Kireev	University of Texas at Austin	United States
Koji	Kita	The University of Tokyo	Japan
Hagen	Klauk	Max Planck Institute for Solid State Research	Germany
Tihomir	Knezevic	Ruder Boskovic Institute	Croatia
Seung Hwan	Ko	Seoul National University	South Korea
Petia	Koprinkova-Hristova	Bulgarian Academy of Sciences	Bulgaria
Selcuk	Kose	University of Rochester	United States
Roza	Kotlyar	Intel Corporation	United States
Randy	Koval	Intel Corporation	United States
Abhinav	Kranti	Indian Institute of Technology (IIT) Indore	India
Abhinav	Kranti	Indian Institute of Technology Indore	India
Yakov	Krasik	Technion—Israel Institute of Technology	Israel
Hannes	Kraus	NASA Jet Propulsion Laboratory	United States
Sriram	Krishnamoorthy	UC Santa Barbara	United States
Zoran	Krivokapic	Advanced Micro Devices Inc.	United States
Martin	Kuball	University of Bristol	United Kingdom
Toshiharu	Kubo	Nagoya Insitute of Technology	Japan
Kelin	Kuhn	Cornell University	United States
Bohdan	Kulyk	University of Aveiro	Portugal
B Sampath	Kumar	Indian Institute of Science	India
Durgesh	Kumar	Nanyang Technological University	Singapore
M. Jagadesh	Kumar	Indian Institute of Technology	India
Priyadarshi	Kumar	Indian Institute of Technology Bombay	India
Shashi	Kumar	National Institute of Technology Meghalaya	India

First Name	Last Name	Affiliation	Country
Yusuke	Kumazaki	Fujitsu Ltd	Japan
Sandip	Kundu	University of Massachusetts System	United States
Kakushima	Kuniyuki	Tokyo Institute of Technology	Japan
Hao-Chung	Kuo	National Chiao Tung University	Taiwan
Yue	Kuo	Texas A&M University	United States
Shin-Ichiro	Kuroki	Hiroshima University	Japan
Rambabu	Kusuma	National Institute of Technology Warangal	India
Masaaki	Kuzuhara	Kwansei Gakuin University	Japan
Jeonghun	Kwak	Seoul National University	South Korea
Joon Seop	Kwak	KENTECH	South Korea
Dae Woong	Kwon	Inha University	South Korea
Hyuck-In	Kwon	Chung-Ang University	South Korea
Jimin	Kwon	Pohang University of Science and Technology	South Korea
Oh-Kyong	Kwon	Hanyang University	South Korea
Uihui	Kwon	Samsung Electronics	South Korea
Avinash	Lahgere	Indian Institute of Technology Kanpur	India
Oliver	Lahr	Universität Leipzig	Germany
Chao Sung	Lai	Chang Gung University	Taiwan
Stefano	Lai	Università di Cagliari	Italy
Wei-Chih	Lai	National Cheng Kung University	Taiwan
Rakesh	Lal	Transphorm Inc.	United States
Linfeng	Lan	South China University of Technology	China
Yann-Wen	Lan	National Taiwan Normal University	Taiwan
Mario	Lanza	King Abdullah University of Science and Technology	Saudi Arabia
Luca	Larcher	Applied Materials Inc.	United States
Sandip	Lashkare	Indian Institute of Technology Bombay	India
Mario	Laudato	Intermolecular Inc.	United States
Nicolas	Laurand	University of Strathclyde	United Kingdom
Bongmook	Lee	North Carolina State University	United States
Byoung Hun	Lee	Pohang University of Science and Technology	South Korea
Chengkuo	Lee	National University of Singapore	Singapore
Choong Hyun	Lee	The University of Tokyo	Japan
Czang-Ho	Lee	University of Waterloo	Canada
Daeseok	Lee	Kwangwoon University	South Korea
Hyeon-Jun	Lee	Daegu Gyeongbuk Institute of Science and Technology	South Korea
Hyung-Seok	Lee	Electronics and Telecommunications Research Institute	South Korea
Hyunjea	Lee	Cornell University	United States
Jaehyun	Lee	Synopsys Inc.	United Kingdom
Jaeseob	Lee	Samsung Display Company Ltd	South Korea
Jang-Sik	Lee	Pohang University of Science and Technology	South Korea
Jeong-Soo	Lee	Pohang University of Science and Technology	South Korea
Jong-Ho	Lee	Seoul National University	South Korea
Joshua	Lee	Institute of Microelectronics	Singapore
Kuan-Wei	Lee	I-Shou University	Taiwan
Kung-Yen	Lee	National Taiwan University	Taiwan
Min-Hung	Lee	National Taiwan Normal University	Taiwan
Rinus	Lee	GlobalFoundries Inc.	United States
Sanghyo	Lee	University of Cambridge	United Kingdom
Sungsik	Lee	Pusan National University	South Korea
Tae-Woo	Lee	Seoul National University	South Korea
Yao-Jen	Lee	Taiwan Semiconductor Research Institute	Taiwan
Yih-Shing	Lee	Minghsin University of Science & Technology	Taiwan
Alberto	Leggieri	Università degli studi di Roma "Tor Vergata"	Italy
Wei	Lei	Southeast University	China
Jaakko	Leppäniemi	VTT Technical Research Center of Finland	Finland

First Name	Last Name	Affiliation	Country
Aidong	Li	Nanjing University	China
Baikui	Li	Shenzhen University	China
Bo	Li	Institute of Microelectronics of Chinese Academy of Sciences	China
Bochang	Li	Xidian University	China
Can	Li	University of Hong Kong	Hong Kong
Cheng	Li	University of California Riverside	United States
Cheng	Li	Xiamen University	China
Dabing	Li	Changchun Institute of Optics Fine Mechanics and Physics Chinese Academy of Sciences	China
Haitong	Li	Purdue University	United States
Huanglong	Li	Tsinghua University	China
Jiun-Yun	Li	National Taiwan University	Taiwan
Jun	Li	Shanghai university	China
Ling	Li	Institute of Microelectronics	China
Liqiang	Li	Tianjin University	China
Mengjiao	Li	University of Southern California	United States
Ming-Huang	Li	National Tsing Hua University	Taiwan
Ming-Jui	Li	Georgia Institute of Technology	United States
Shaojuan	Li	Changchun Institute of Optics Fine Mechanics and Physics Chinese Academy of Sciences	China
Wei	Li	Shaanxi University of Science & Technolog	United States
Wei-Chang	Li	NTU College of Engineering	Taiwan
Wenshen	Li	Cornell University	United States
Xianbo	Li	Sun Yat-sen University	China
Xiangdong	Li	Xidian University	China
Xifeng	Li	Shanghai University	China
Xueqing	Li	Tsinghua University	China
Yan-Qing	Li	East China Normal University Liyan	China
Yi	Li	Huazhong University of Science and Technology	China
Yingtao	Li	Lanzhou University	China
Yiyang	Li	Univesity of Michigan	United States
Yuzhi	Li	South China University of Technology	China
Zehong	Li	University of Electronic Science and Technology of China	China
Lin	Liang	Huazhong University of Science and Technology	China
Wei	Liang	Globalfoundries Inc.	United States
Zongcun	Liang	Sun Yat-sen University	China
Congwei	Liao	Peking University	China
Lei	Liao	Hunan University	China
Lei	Liao	Wuhan University	China
Meiyong	Liao	National Institute for Materials Science	Japan
Milton	Liao	National Taiwan University	Taiwan
Min	Liao	Xiangtan University	China
Daniel	Lichtenwalner	Wolfspeed	United States
Bohan	Lin	Tsinghua University	China
Chien-Chung	Lin	National Chiao Tung University College of Photonics	Taiwan
Chih-Lung	Lin	National Cheng Kung University	Taiwan
Chun	Lin	National Chiao Tung University	Taiwan
Dong	Lin	Jimei University	China
Hornng-Chih	Lin	National Chiao Tung University	Taiwan
Jing-Yu	Lin	South China University of Technology	China
Po Jung	Lin	Global Wafers Company Ltd	Taiwan
Xi-Wei	Lin	Synopsys Inc.	United States
Ya	Lin	Northeast Normal University	China
Yen-Kai	Lin	Samsung Semiconductor Inc. USA	United States

First Name	Last Name	Affiliation	Country
Yo-Shen	Lin	National Central University	Taiwan
Yuxuan	Lin	MIT	United States
Zehao	Lin	Purdue University	United States
Erik	Lind	Lund University	Sweden
Alvydas	Lisauskas	Frankfurt University	Germany
Chee Wee	Liu	National Taiwan University	Taiwan
Chuan	Liu	Sun Yat-sen University	China
Dong	Liu	University of Wisconsin-Madison	United States
Fang	Liu	Tsinghua University	China
Gang	Liu	Shanghai Jiao Tong University	China
Haitao	Liu	Micron Technology Inc.	United States
Han-Yin	Liu	National Sun Yat-sen University	Taiwan
Jia-Zhe	Liu	Global Wafers Company Ltd	Taiwan
Jing	Liu	Tianjin University	China
Ming	Liu	Institute of Microelectronics of Chinese Academy of Sciences	China
Po-Tsun	Liu	National Chiao Tung University	Taiwan
Samuel	Liu	The University of Texas at Austin	United States
Tong	Liu	Micron Technology Inc.	United States
Wen	Liu	Xi'an Jiaotong-Liverpool University	China
Wenxin	Liu	Institute of Electronics, CAS	China
Xian	Liu	Silicon Storage Technolog	United States
Xinke	Liu	Shenzhen University	China
Xizhe	Liu	Jilin University	China
Xueqing	Liu	Rensselaer Polytechnic Institute	United States
Yong	Liu	Hong Kong University of Science and Technology	Hong Kong
Yuhuai	Liu	Zhengzhou University	China
Zhan	Liu	Intel Corporation	United States
Zhaojun	Liu	Southern University of Science and Technology	China
Zhenbang	Liu	Institute of Applied Electronics, China Academy of Engineering Physics	China
Zhihong	Liu	Singapore-MIT Alliance for Research and Technology	Singapore
Guo-Qiang	Lo	Adv Micro Foundry	United States
Yu-Hwa	Lo	University of California San Diego	United States
Patrick	Lomenzo	NaMLab gGmbH	Germany
Shibing	Long	University of Science and Technology of China	China
Neophytos	Lophitis	University of Nottingham	United Kingdom
Leo	Lorenz	Infineon Technologies China Company Ltd	China
Liang	Lou	Shanghai Industrial μ Technology Research Institute	China
Nicolas	Loubet	IBM	United States
Anni	Lu	Georgia Institute of Technology College of Engineering	United States
Darsen	Lu	National Cheng Kung University	Taiwan
Hai	Lu	Nanjing University	China
James J.-Q.	Lu	Rensselaer Polytechnic Institute	United States
Jiang	Lu	Institute of Microelectronics of Chinese Academy of Sciences	China
Lei	Lu	Hong Kong University of Science and Technology	Hong Kong
Lei	Lu	Peking University	China
Tao-Cheng	Lu	Macronix International Company Ltd.	Taiwan
Xing	Lu	Sun Yat-sen University	China
Yipeng	Lu	University of California, Davis	United States
Mathieu	Luisier	ETH Zurich	Switzerland
Mark	Lundstrom	Purdue University	United States
Guang-Li	Luo	National Nano Device Laboratories	Taiwan
Guo-Lun	Luo	University of California, Davis	United States

First Name	Last Name	Affiliation	Country
Jingting	Luo	Shenzhen University	China
Jirun	Luo	Institute of Electronics	China
Jun	Luo	The Institute of Microelectronics of Chinese Academy of Science	China
Linbao	Luo	Hefei University of Technology	China
Qing	Luo	Institute of Microelectronics of Chinese Academy of Sciences	China
Xiao Rong	Luo	University of Electronic Science and Technology of China	China
Yuan-Chun	Luo	Georgia Institute of Technology	United States
Zhaochun	Luo	Peking University	China
Zhengdong	Luo	Xidian University	China
Rudi	Lussana	Politecnico di Milano	Italy
Josef	Lutz	Chemnitz University of Technology	Germany
Hangbing	Lv	Institute of Microelectronics of Chinese Academy of Sciences	China
Yuanjie	Lv	Hebei Semiconductor Research Institute	China
Alexander	Lyublinsky	Physical-Technical Institute	Russia
Xiaohua	Ma	Xidian University	China
Xio	Ma	Qorvo	United States
Zhenqiang (Jack)	Ma	University of Wisconsin-Madison	United States
Oreste	Madia	Taiwan Semiconductor Manufacturing Company Europe BV	Belgium
Takuya	Maeda	Cornell University	United States
Takuya	Maeda	Kyoto University	Japan
Bikram	Mahajan	Purdue University	United States
Santanu	Mahapatra	Indian Institute of Science	India
Souvik	Mahapatra	Indian Institute of Technology Bombay	India
Peyman	Mahouti	Istanbul Cerrahpas University	United States
Siddheswar	Maikap	Chang Gung University	Taiwan
Luca	Maiolo	CNR	Italy
Santanu	Maity	Indian Institute of Engineering Science and Technology	India
Shubhankar	Majumdar	National Institute of Technology Meghalaya	India
Swatilekha	Majumdar	IMEC	Belgium
B. Gunnar	Malm	Kungliga Tekniska Hogskolan	Sweden
Anna	Malmros	Chalmers University of Technology	Sweden
Timothy	Maloney	Intel Corporation	United States
Cristell	Maneux	Université de Bordeaux	France
Alan	Mantooth	University of Arkansas	United States
Tomas	Manzaneque Garcia	Delft University of Technology	The Netherlands
Hongying	Mao	Hangzhou Normal University	China
Luigi	Mariucci	Consiglio Nazionale delle Ricerche	Italy
Antonio	Martinez	Swansea University	United Kingdom
Diego	Martín-Martín	Universidad Rey Juan Carlos	Spain
Jorge	Martins	CENIMAT	Portugal
Rodrigo	Martins	Universidade Nova de Lisboa	Portugal
Marta	Mas-Torrent	Instituto de Ciencia de Materiales de Barcelona	Spain
Jimson	Mathew	Indian Institute of Technology Patna	India
Elison	Matioli	École Polytechnique Fédérale de Lausanne	Switzerland
Mallory	Mativenga	Kyung Hee University	South Korea
Tomoko	Matsudai	Toshiba Corporation	Japan
Hiroyuki	Matsui	Yamagata University—Yonezawa Campus	Japan
Narasimha Rao	Mavilla	Synopsys India Pvt. Ltd	India
Sergey	Maximenko	US Naval Research Laboratory	United States
Sudip	Mazumder	University of Illinois	United States

First Name	Last Name	Affiliation	Country
Colin	Mcandrew	NXP Semiconductors NV	United States
Connor	McClellan	Stanford University	United States
Farid	Medjdoub	CNRS Délégation Ile-de-France Ouest et Nord	France
Adnan	Mehonic	UCL	United Kingdom
Saumitra	Mehrotra	Maxim Integrated	United States
Zengxia	Mei	Institute of Physics Chinese Academy of Sciences	China
Tilo	Meister	Technische Universität Dresden	Germany
Matteo	Meneghini	University of Padova	Italy
Stephan	Menzel	Forschungszentrum Julich GmbH	Germany
Meyya	Meyyappan	NASA Ames Research Center	United States
Shinji	Migita	AIST	Japan
Slobodan	Mijalkovic	Silvaco Europe	United Kingdom
Thomas	Mikolajick	Technische Universität Dresden	Germany
Nicholas	Miller	Air Force Research Laboratory	United States
Takanori	Mimura	Gakushuin University	Japan
Sun-Hong	Min	Seoul National University	South Korea
Takeo	Minari	MANA-NIMS	Japan
Guru	Mishra	National Institute of Technology	India
Varun	Mishra	Intel Corporation	United States
Tomohiko	Mitani	Kyoto University	Japan
Arkadeep	Mitra	The University of Texas at Dallas	United States
Sushant	Mittal	Indian Institute of Technology Varanasi	India
Yasuyuki	Miyamoto	Tokyo Institute of Technology	Japan
Makoto	Miyoshi	Nagoya Institute of Technology	Japan
Fei	Mo	Kioxia Corporation	Japan
Stefan	Moench	Fraunhofer-Institut für Angewandte Festkörperphysik	Germany
Peter	Moens	ON Semiconductor	Belgium
Suzanne	Mohney	Penn State University	United States
Majid	Mohseni	Shahid Beheshti University	Iran
Joel	Molina	INAOE	Mexico
Sandip	Mondal	Indian Institute of Science	India
Dong-Il	Moon	NASA Ames Research Center	United States
Yi-Shien	Mor	TSMC	Taiwan
David	Moran	University of Glasgow	United Kingdom
Nobuya	Mori	Osaka University	Japan
Zohreh	Movahedian	Shahrood University of Technology	Iran
Hema	Movva	University of Texas at Austin	United States
Sivakumar	Mudanai	Intel Corporation	United States
Adnan	Mujahid	Punjab University	Pakistan
Shaibal	Mukherjee	Indian Institute of Technology Indore	India
Subhadeep	Mukhopadhyay	Intel Corporation	United States
Halid	Mulaosmanovic	GlobalFoundries Inc.	Germany
Niko	Münzenrieder	Free University of Bozen-Bolzano	Italy
Paul	Muralt	École Polytechnique Fédérale de Lausanne	Switzerland
Andrey	Muraviev	University of Central Florida	United States
Roberto Stack	Murphy-Arteaga	National Inst for Astrophysics Optics and Electronics	Mexico
Karthick	Murugesan	University of Cambridge	United Kingdom
Artem	Musienko	Helmholtz-Zentrum Berlin für Materialien und Energie GmbH	Germany
Sanghoon	Myung	Samsung Electronics Device Solutions	South Korea
Harsh	Naik	Infineon Technologies Americas Corporation	United States
Pradeep	Nair	Indian Institute of Technology Bombay	India
Satoshi	Nakazawa	Panasonic Corporation	Japan
Tianxiang	Nan	Tsinghua University	China
Lis	Nanver	University of Twente	The Netherlands
Rakhi	Narang	University of Delhi	India

First Name	Last Name	Affiliation	Country
Aravind	Narayanan	Tokyo Institute of Technology	Japan
Sudarshan	Narayanan	Western Digital Technologies Inc.	United States
Federico	Nardi	Applied Materials Inc.	United States
Digbijoy	Nath	Indian Institute of Science	India
Gabriele	Navarro	CEA-LETI MINATEC	France
Nupur	Navlakha	University of Texas at Austin	United States
Luca	Nela	École Polytechnique Fédérale de Lausanne	Switzerland
Philip	Neudeck	NASA	United States
Geok Ing	Ng	Nanyang Technological University	Singapore
Tien Khee	Ng	King Abdullah University of Science and Technology	Saudi Arabia
Wai Tung	Ng	University of Toronto	Canada
Thanh	Nguyen	Griffith University Griffith Sciences	Australia
Kai	Ni	Vanderbilt University	United States
Gianluca	Nicosia	Micron Technology Inc.	United States
Dmitri	Nikonov	Intel Corporation	United States
Hussein	Nili	University of California Santa Barbara	United States
Hong-Long	Ning	South China University of Technology	China
Zhijun	Ning	Shanghai Tech University	China
Tomonori	Nishimura	The University of Tokyo	Japan
Tatsuya	Nishiwaki	Toshiba Semiconductor Company	Japan
Iulian	Nistor	mqSemi AG	Switzerland
Guofu	Niu	Auburn University	United States
Zhichuan	Niu	State Key Laboratory for Superlattices and Microstructures	China
Kazuki	Nomoto	Cornell University	United States
Kenji	Nomura	University of California San Diego	United States
Arto	Nurmikko	Brown University	United States
Gregory	Nusinovich	University of Maryland	United States
Borna	Obradovic	TCAD	United States
Shunri	Oda	Tokyo Institute of Technology	Japan
Dongyeon	Oh	Hynix Semiconductor Inc.	South Korea
Saeroonter	Oh	Hanyang University	South Korea
Sangheon	Oh	University of California San Diego	United States
Shun-Ichiro	Ohmi	Tokyo Institute of Technology—Suzukakedai Campus	Japan
Hiromichi	Ohta	Hokkaido University	Japan
Toshiyuki	Oishi	Saga University	Japan
Aaron	Okie	Northrop Grumman Space Technology	United States
Phil	Oldiges	Sandia National Laboratories	United States
Marius	Orlowski	Virginia Tech	United States
Adelmo	Ortiz-Conde	Universidad Simon Bolivar	Venezuela
Clemens	Ostermaier	Infineon Technologies	Austria
Vaibhav	Ostwal	Purdue University	United States
Hiroyuki	Ota	National Institute of Advanced Industrial Science and Technology	Japan
Jack	Ou	California State University Northridge	United States
Anibal	Pacheco-Sanchez	Autonomous University of Barcelona	Spain
Pradeep	Pai	Intel Corporation	United States
Marco	Pala	Centre de Nanosciences et Nanotechnologies	France
Pierpaolo	Palestri	Universita degli Studi di Udine	Italy
Emiliano	Pallecchi	IEMN	France
Feng	Pan	Tsinghua University	China
Liyang	Pan	Tsinghua University	China
Tung-Ming	Pan	Chang Gung University	Taiwan
Amritanshu	Pandey	Indian Institute of Technology	India
Shesh Mani	Pandey	GlobalFoundries	Singapore
Danilo	Pani	University of Cagliari	Italy

First Name	Last Name	Affiliation	Country
Claudio	Paoloni	Lancaster University	United Kingdom
Jin-Seong	Park	Hanyang University	South Korea
Jun-Young	Park	Chungbuk National University	South Korea
Keechan	Park	Konkuk University	South Korea
Min Hyuk	Park	Seoul National University	South Korea
Min Hyuk	Park	Pusan National University	South Korea
Min-Kyu	Park	Seoul National University	South Korea
Minseo	Park	Auburn University	United States
Sang-Hee	Park	KAIST	South Korea
Sung Kyu	Park	Chung-Ang University	South Korea
Shubhra	Pasayat	University of Wisconsin-Madison	United States
John	Pasour	Naval Research Laboratory	United States
Bishnu	Patra	Intel Corporation	United States
Erin	Patrick	University of Florida	United States
Paolo	Pavan	Universita di Modena e Reggio Emilia	Italy
Marcelo	Pavanello	Centro Universitario da FEI	Brazil
Stephen	Pearton	University of Florida	United States
Vincenzo	Pecunia	Simon Fraser University	Canada
Vladimir	Pejovic	IMEC	Belgium
Sara	Pellegrini	STMicroelectronics	United Kingdom
Chao	Peng	China Electronic Product Reliability and Environmental Testing Research Institute	China
Lan	Peng	IMEC	Belgium
Yue	Peng	Xidian University	China
Ashish Verma	Penumatcha	Intel Corporation	United States
Oleg	Penzin	Synopsys Inc.	United States
Luis	Pereira	Universidade Nova de Lisboa FCT	Portugal
Julien	Pernot	Institut Néel	France
Joshua	Perozek	Massachusetts Institute of Technology	United States
Komalan	Perumkunnil	IMEC	Belgium
Milan	Pešić	Applied Materials Inc.	United States
Nikolai	Peskov	Russian Academy of Sciences	Russia
Rebecca	Peterson	University of Michigan	United States
Luisa	Petti	Libera Università di Bolzano	Italy
Jonathan	Petticrew	University of Sheffield	United Kingdom
Martin	Pfost	Technische Universität Dortmund	Germany
Gianluca	Piazza	Carnegie Mellon University	United States
Enrico	Piccinini	ARCES Research Center	Italy
Daniel	Piedra	Analog Devices Inc. Wilmington	United States
Maykel	Piedrahita	Universidad de Guadalajara	Mexico
Dominique	Planson	Université de Lyon	France
Dionyz	Pogany	Vienna University of Technology	Austria
Antonio	Politano	University of L'Aquila	Italy
Mirko	Poljak	University of Zagreb	Croatia
Niels	Posthuma	IMEC	Belgium
Ghobad Behzadi	Pour	Islamic Azad University	Iran
Ali	Pourghaderi	Samsung Electronics	South Korea
Amit	Prakash	Crossbar Inc.	United States
Chetan	Prasad	Intel Corporation	United States
Tatiana	Prutskij	Benemérita Universidad Autónoma de Puebla	Mexico
Francesco Maria	Puglisi	Universita' di Modena e Reggio Emilia	Italy
Joaquim	Puigdollers	Universitat Politècnica Catalunya	Spain
Yinghua	Qiu	Shandong University	China
Rüdiger	Quay	Fraunhofer IAF	Germany
Ujwal	Radhakrishna	Indian Institute of Technology Madras	India
Bruce	Rae	STMicroelectronics	United Kingdom

First Name	Last Name	Affiliation	Country
Nagarajan	Raghavan	Singapore University of Technology & Design	Singapore
Shyam	Raghunathan	Micron Technology Inc.	Singapore
Nivedita	Rai	Indian Institute of Technology Indore	India
Aditya	Raj	University of California Santa Barbara	United States
Nitin	Rajan	University of California at Santa Barbara	United States
S. Srinivasulu	Raju	National Institute of Technology (NIT System)	India
Shriram	Ramanathan	Purdue University	United States
Sivaramakrishnan	Ramesh	IMEC	Belgium
Stephen	Ramey	Intel Corporation	United States
Vikas	Rana	STMicroelectronics pvt Ltd Greater Noida	India
Sanjay	Rangan	Intel Corporation	United States
Arman	Rashid	University of Arkansas Fayetteville	United States
Joseph Daniel	Rathnasami	Annamalai University	India
Pramod	Reddy	North Carolina State University	United States
William	Redman-White	University of Southampton	United Kingdom
Susanna	Reggiani	Università di Bologna	Italy
David	Reid	Synopsys Inc.	United States
Chenhao	Ren	University of California Davis	United States
Na	Ren	Zhejiang University	China
Zeyang	Ren	Xidian University	China
Pavel Ivanoff	Reyes	Rutgers State University New Brunswick	United States
Reto	Rhyner	Synopsys Switzerland LLC	Switzerland
Aditya	Rianjanu	Inst Teknol Sumatera	Indonesia
Craig	Riddet	Synopsys Inc.	United Kingdom
Denis	Rideau	STMicroelectronics	France
Rafael	Rios	Samsung	United States
Serena	Rizzolo	Airbus Defence and Space SAS	France
Patrick	Roblin	Ohio State University	United States
Fabrizio	Roccaforte	CNR-IMM	Italy
Michael	Rodder	University of Texas at Austin	United States
Noel	Rodriguez	Universidad de Granada	Spain
Albert	Roitman	Communications and Power Industries	Canada
Brian	Romanczyk	University of California, Santa Barbara	United States
Tabrizian	Roosbeh	University of Florida	United States
Niklas	Rorsman	Chalmers University of Technology	Sweden
Vladislav	Rostov	Institute of High Current Electronics	Russia
Nicolas	Rouger	CNRS	France
Francois	Roy	STMicroelectronics	France
Vellaisamy	Roy	City University of Hong Kong	Hong Kong
Andrey	Rozhnev	Instituta radiotehniki i elektroniki Saratovskij filial	Russia
Cunjun	Ruan	Beihang University	China
Phil	Rutter	iDEAL Semiconductor	United States
Nikita	Ryskin	Russian Academy of Sciences	Russia
Sei-Hyung	Ryu	Wolfspeed, Inc.	United States
Ali	Saadat	University of Texas at Dallas	United States
Svilen	Sabchevski	Balgarska akademija na naukite	Bulgaria
Angada	Sachid	Applied Materials Inc.	United States
Angada B.	Sachid	University of California Berkeley	United States
Sharif Md	Sadaf	INRS	United States
Sunny	Sadana	Indian Institute of Technology Bombay	India
Dipankar	Saha	Indian Institute of Technology Bombay	India
Samar K.	Saha	Prospicient Devices	United States
Shubham	Sahay	Indian Institute of Technology Kanpur	India
Wataru	Saito	Kyushu University	Japan
Shigeki	Sakai	National Institute of Advanced Industrial Science and	Japan
Jayatika	Sakhujia	Indian Institute of Technology Bombay	India

First Name	Last Name	Affiliation	Country
Katsuyuki	Sakuma	IBM	United States
Sayeeef	Salahuddin	University of California, Berkeley	United States
Rakshith	Saligram	Georgia Institute of Technology	United States
Stefano	Salvatori	Universita degli Studi Niccolo Cusano	Italy
Subhranu	Samanta	National University of Singapore	Singapore
Mohammad	Samizadeh Nikoo	École Polytechnique Fédérale de Lausanne	Switzerland
Sergey	Samsonov	Institute of Applied Physics	Russia
Venkateswarlu	Sankatali	IMEC	Belgium
Saurabh	Sant	Indian Institute of Technology Bombay	India
Vivek	Saraswat	Indian Institute of Technology Bombay	India
Vivek	Saraswat	University of Wisconsin-Madison	United States
Kohei	Sasaki	Novel Crystal Technology	Japan
Nandakumar	Sasidharan		
	Rajalekshmi	IBM	Switzerland
Jagabar	Sathik	SRM Institute of Science and Technology	India
Alexander	Satka	Slovak University of Technology	Slovakia
Shin-Ichiro	Sato	Japan Atomic Energy Agency	Japan
Matlabjon	Sattorov	Seoul National University	South Korea
Paul	Saunier	Qorvo	United States
Sneh	Saurabh	Indraprastha Institute of Information Technology	India
Andrey	Savilov	Institute for Applied Physics	Russia
Tanuj	Saxena	NXP Semiconductors	United States
Shehrin	Sayed	University of California Berkeley	United States
Edl	Schamiloglu	University of New Mexico	United States
Alexander	Schmidt	Samsung Electronics	South Korea
Jurriaan	Schmitz	University of Twente	The Netherlands
Harald	Schneider	Helmholtz-Zentrum Dresden-Rossendorf	Germany
Andries	Scholten	NXP Semiconductors	The Netherlands
Ronald	Schrimpf	Vanderbilt University	United States
Patrick	Schuh	Hensoldt Sensors GmbH	Germany
Fabio	Sebastiano	Technische Universiteit Delft	The Netherlands
Luca	Selmi	Universita degli Studi di Udine	Italy
Abhronil	Sengupta	Penn State University	United States
Junji	Senzaki	NAIST	Japan
Jung Hun	Seo	University at Buffalo	United States
Hyejeong	Seong	Korea Institute of Science and Technology	South Korea
Dong	Seup Lee	Texas Instruments	United States
Davood	Shahrjerdi	New York University	United States
Chong-Xin	Shan	Zhengzhou University	China
Dashan	Shang	Institute of Microelectronics of Chinese Academy of Sciences	China
Ravi	Shankar	STMicroelectronics Pte Ltd	Singapore
Tao	Shao	Chinese Academy of Sciences	China
Pankaj	Sharma	Micron Technology Inc.	United States
Harry	Shaw	NASA	United States
Mst Shamim Ara	Shawkat	Florida International University	United States
Shyh-Chiang	Shen	Georgia Institute of Technology	United States
Wenzhong	Shen	Shanghai Jiao Tong University	China
Xing	Sheng	Tsinghua University	China
Yanli	Shi	Yunnan University	China
Jia-Min	Shieh	National Nano Device Laboratories	Taiwan
Andy	Shih	École de Technologie Supérieure	Canada
Pao-Chuan	Shih	Massachusetts Institute of Technology	United States
Wonbo	Shim	Seoul National University of Science and Technology	South Korea
Takao	Shimizu	National Institute for Materials Science	Japan
Changhwan	Shin	Korea University	South Korea

First Name	Last Name	Affiliation	Country
Sanghoon	Shin	Intel Corporation	United States
Shoso	Shingubara	Kansai University	Japan
Keisuke	Shinohara	Teledyne Scientific & Imaging	United States
Mahmoud	Shousha	Wuerth Elektronik eiSos GmbH & Company KG	Germany
Mayank	Shrivastava	Indian Institute of Science	India
Shalini	Shrivastava	Indian Institute of Technology Bombay	India
Mengwei	Si	Shanghai Jiao Tong University	China
Moiz	Siddiqi	Metron Inc.	United States
Urmita	Sikder	University of California Berkeley	United States
Scott	Sills	Micron Technology Inc.	United States
Helena	Silva	University of Connecticut	United States
Luca	Silvestri	Synopsys Switzerland LLC	Switzerland
Eddy	Simoen	IMEC	Belgium
Jagar	Singh	GlobalFoundries Inc.	United States
Manikant	Singh	University of Bristol	United Kingdom
Ranveer	Singh	University of Wisconsin-Madison	United States
Shakti	Singh	Khalifa University	United Arab Emirates
Uttam	Singiseti	University at Buffalo	United States
Rajat	Sinha	GlobalFoundries Inc.	India
Henning	Sirringhaus	University of Cambridge	United Kingdom
Andrei	Slavin	Oakland University	United States
Stefan	Slesazek	NaMLab GmbH	Germany
Philippe	Smet	Ghent University	Belgium
Shahadat	Sohel	The Ohio State University	United States
Reza	Soleimanzadeh	École Polytechnique Fédérale de Lausanne	Switzerland
Kyung-Ah	Son	HRL Laboratories	United States
Aimin	Song	University of Manchester	United Kingdom
Cheng	Song	Tsinghua University	China
Jizhou	Song	Zhejiang University	China
Yi	Song	IBM	United States
Marko	Sonkki	Ericsson Antenna Technology Germany GmbH	Germany
Andrea	Spanu	University of Cagliari	Italy
James	Speck	University of California Santa Barbara	United States
Radim	Špetík	ON Semiconductor	Czech Republic
Radu	Sporea	University of Surrey	United Kingdom
Tathagata	Srimani	Massachusetts Institute of Technology	United States
Purushothaman	Srinivasan	GlobalFoundries Inc.	United States
Siwapon	Srisonphan	Kasetsart University	Thailand
Vishnu	Srivastava	CSIR-CEERI Pilani	India
Jan	Stake	Chalmers University of Technology	Sweden
Spyros	Stathopoulos	University of Southampton	United Kingdom
Stephan	Steinhauer	KTH Royal Institute of Technology	Sweden
Arno	Stockman	BelGaN	Belgium
Sebastiano	Strangio	Università degli Studi di Pisa	Italy
Pin	Su	National Chiao Tung University	Taiwan
Alexandre	Subirats	Micron Technology Inc.	United States
Arulkumaran	Subramaniam	Nanyang Technological University	Singapore
Akhil	Sudarasanan	Indian Institute of Technology Hyderabad	India
Tetsuya	Suemitsu	Tohoku University	Japan
Chang	Suh	Texas Instruments	United States
R. Scott	Summerfelt	Texas Instruments	United States
Qian	Sun	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Sheng	Sun	Peking University	China
Jordi	Sune	Universidad Autónoma de Barcelona	Spain
Hoon	Sung	Intel Corporation	United States

First Name	Last Name	Affiliation	Country
Woongje	Sung	State University of New York Polytechnic Institute	United States
Ateeq	Suria	Stanford University	United States
Teruo	Suzuki	Socionext Inc.	Japan
Viktor	Sverdlov	Technical University of Vienna	Austria
Victor V.	Sysoev	Yuri Gagarin State Technical University of Saratov	Russia
Pascal	't Hart	TU Delft	The Netherlands
Tomihisa	Tachibana	National Institute of Advanced Industrial Science and Technology	Japan
Ishibashi	Tadao	NTT	Italy
Marko	Tadjer	Naval Research Laboratory	United States
Maher	Tahhan	Raytheon Technologies Corporation	United States
Huiling	Tai	University of Electronic Science and Technology of China	China
Ya Hsiang	Tai	National Chiao Tung University	Taiwan
Ketankumar	Tailor	Intel Foundation	United States
Kosuke	Takenaka	Osaka University	Japan
Kiyoshi	Takeuchi	The University of Tokyo	Japan
Srinivasa Reddy	Tamalampudi	New York University Abu Dhabi	United Arab Emirates
Shingo	Tamaru	National Institute of Advanced Industrial Science and Technology Tsukuba Center Tsukuba Central	Japan
Chih Shan	Tan	National Chiao Tung University	Taiwan
Aiwei	Tang	Beijing Jiaotong University	China
Jianshi	Tang	Tsinghua University	China
Tien-Hao	Tang	UMC	Taiwan
Wing Man	Tang	University of Hong Kong	Hong Kong
Xiaoyan	Tang	Xidian University	China
Zhikai	Tang	Efficient Power Conversion Corporation	United States
Lu-Qi	Tao	University of Science and Technology Beijing	China
Milan	Tapajna	Institute of Electrical Engineering SAS	Slovakia
Rabih	Tauk	Lebanese University Faculty of Science	Lebanon
Jeffrey	Teng	Georgia Institute of Technology	United States
Tomohide	Terashima	Mitsubishi Electric Corporation	Japan
Kornelius	Tetzner	Ferdinand-Braun-Institut Leibniz-Institut fur Hochstfrequenztechnik	Germany
Paragkumar	Thadesar	QUALCOMM Inc.	United States
Sudhakar Babu	Thanikanti	UNITEN	Malaysia
Aaron	Thean	National University of Singapore	Singapore
Han Wui	Then	Intel Corporation	United States
Christoforos	Theodorou	Grenoble INP	France
Fabian	Thome	Fraunhofer IAF	Germany
Muthiah	Thottappan	Indian Institute of Technology Varanasi	India
Manfred	Thumm	Karlsruhe Institute of Technology	Germany
He	Tian	Tsinghua University	China
Yonghui	Tian	Lanzhou University	China
David	Ting	Jet Propulsion Laboratory	United States
Pramod	Tiwari	Indian Institute of Technology Patna	India
Shree Prakash	Tiwari	Indian Institute of Technology Jodhpur	India
Katsuhiko	Tomioka	Hokkaido University	Japan
Roman	Torgashov	Russian Academy of Sciences	Russia
Akira	Toriumi	University of Tokyo	Japan
Nikolay	Torkhov	Tomsk State University of Control Systems and Radioelectronics	Russia
Vishal	Trivedi	Freescale Semiconductor Inc.	United States
Huynh-Bao	Trong	Taiwan Semiconductor Manufacturing Company Ltd	Canada
Feng-Yu	Tsai	National Taiwan University	Taiwan

First Name	Last Name	Affiliation	Country
Jung-Hui	Tsai	National Kaohsiung Normal University	Taiwan
Tsung-Ming	Tsai	National Sun Yat-sen University	Taiwan
Charalampos	Tsiouostas,	National Technical University of Athens	Greece
Toshiyuki	Tsuchiya	Kyoto University	Japan
Hiroshi	Tsuji	NHK Science and Technical Research Lab	Japan
Soichiro	Tsujino	Paul Scherrer Institut	Switzerland
Gen	Tsutsui	IBM	United States
Takuya	Tsutsumi	NTT Corporation	Japan
Christian	Tückmantel	University of Wuppertal	Germany
Ahmet	Tura	Intel Corporation	United States
Stanislav	Tyaginov	IMEC	Belgium
Wasi	Uddin	Indian Institute of Technology Delhi	India
Daisuke	Ueda	Kyoto Kogei Sen'i Daigaku	Japan
Tetsuzo	Ueda	Matsushita Electric Industrial Company Ltd	Japan
Tsutomu	Uesugi	Toyota Central R&D Labs., Inc.	Japan
Giacomo	Ulisse	Goethe-Universität Frankfurt am Main	Germany
Navnidhi	Upadhyay	University of Massachusetts Amherst	United States
Yukiharu	Uraoka	NAIST	Japan
Michael	Uren	University of Bristol	United Kingdom
Muhammad	Usman	KTH Royal Institute of Technology	Sweden
Muhammad	Usman	National Centre for Physics	Pakistan
Senthil	Vadakupudhu Palayam	IMEC	Belgium
Senthil Srinivasan	Vadakupudhu- Palayam	University of Stuttgart	Germany
Ilia	Valov	Forschungszentrum Jülich GmbH	Germany
Kees	Van Der Zouw	University of Twente	The Netherlands
William	Vandenbergh	University of Texas at Dallas	United States
Venkata Narayana Rao	Vanukuru	GlobalFoundries Inc.	United States
Enrico	Varesi	Micron Technology Inc.	Italy
Dhanooop	Varghese	Texas Instruments	United States
Vladislav	Vashchenko	Maxim Integrated	United States
Reinaldo	Vega	IBM	United States
Alin	Velea	Institutul National de Cercetare-Dezvoltare Pentru Fizica	Romania
Anabela	Veloso	IMEC	Belgium
Umamaheswara	Vemulapati	Hitachi ABB Power Grids	Switzerland
Claudio	Verona	Università di Roma "Tor Vergata"	Italy
Devin	Verreck	IMEC	Belgium
Andrei	Vescan	RWTH Aachen University	Germany
Vincenzo	Vinciguerra	STMicroelectronics	Switzerland
Alexander	Vlasov	Naval Research Laboratory	United States
Jan	Vobecky	Hitachi ABB Power Grids	Switzerland
Joachim	Vollbrecht	University of Postdam	Germany
Jan	Voves	Ceske Vysoke Ucení Technické v Praze	Czech Republic
Pratik	Vyas	The University of Texas at Dallas	United States
John	Wager	Oregon State University	United States
Sigurd	Wagner	Princeton University	United States
Muhammad A.	Wahab	Intel Corporation	United States
Changjin	Wan	Nanjing University	China
Jing	Wan	Fudan University	China
Qing	Wan	Nanjing University	China
Han	Wang	University of Southern California	United States
Hong	Wang	Xidian University	China
Huasheng	Wang	Soochow University	China

First Name	Last Name	Affiliation	Country
I-Ting	Wang	National Chiao Tung University	Taiwan
Jing	Wang	University of South Florida	United States
Lin	Wang	Shanghai Institute of Technical Physics CAS	China
Linzhi	Wang	Tianma Micro-Electronics Company Ltd	China
Maojun	Wang	Peking University	China
Mingxiang	Wang	Soochow University	China
Nan	Wang	Institute of Microelectronics, Agency for Science, Technology and Research	Singapore
Panni	Wang	Western Digital Corporation	United States
Ping	Wang	University of Michigan	United States
Renjie	Wang	McGill University	Canada
Ruidi	Wang	University of Electronic Science and Technology of China	China
Runsheng	Wang	Peking University	China
Sheng Kai	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Shui Jinn	Wang	National Cheng Kung University	Taiwan
Shujie	Wang	Henan University	China
Sui-Dong	Wang	Soochow University	China
Taifang	Wang	École Polytechnique Fédérale de Lausanne	Switzerland
Wei	Wang	Jilin University	China
Wei	Wang	Peng Cheng Laboratory	China
Xi	Wang	Xi'an University of Technology	China
Xiaolei	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Xiaomu	Wang	Nanjing University	China
Xingsheng	Wang	Huazhong University of Science and Technology	China
Xinhua	Wang	Institute of Microelectronics of Chinese Academy of Sciences	China
Xinwei	Wang	Peking University Shenzhen Graduate School	China
Yijiao	Wang	Beihang University	China
Yiming	Wang	Shandong University	China
Yue	Wang	Xi'an Jiaotong University	China
Zheng	Wang	Georgia Institute of Technology	United States
Zhenxing	Wang	National Center for Nanoscience and Nanotechnology	China
Zhiguang	Wang	Xi'an Jiaotong University	China
Zhongqiang	Wang	Northeast Normal University	China
Zhongrui	Wang	University of Hong Kong	Hong Kong
Zongwei	Wang	Peking University	China
Atom	Watanabe	IBM	United States
Justin	Weber	Intel Corporation	United States
Jin	Wei	Hong Kong University of Science and Technology	Hong Kong
Jin	Wei	Peking University	China
Xianlong	Wei	Peking university	China
Zhanhua	Wei	Huaqiao University	China
Nils	Weimann	University of Duisburg-Essen	Germany
Martin	Weis	Slovak University of Technology	Slovakia
Dennis	Weller	Karlsruher Institut für Technologie	Germany
Deqi	Wen	Michigan State University	United States
Christian	Wenger	IHP Microelectronics GmbH	Germany
Lars-Erik	Wernersson	Lund University	Sweden
Christian	Wetzel	Rensselaer Polytechnic Institute	United States
Jonathan	Wierer	Lehigh University	United States
Nicholas	Williams	Northwestern University	United States
Madison	Wilson	University of California San Diego	United States
Hui-Yung	Wong	San Jose State University	United States

First Name	Last Name	Affiliation	Country
Joel	Wong	HRL Laboratories	United States
Man	Wong	The Hong Kong University of Science and Technology	Hong Kong
Man Hoi	Wong	University of Massachusetts Lowell	United States
Matthew	Wong	UC Santa Barbara	United States
William	Wong	University of Waterloo	Canada
Jiyong	Woo	Kyungpook National University	South Korea
John	Wrbanek	NASA John H Glenn Research Center	United States
Chao-Hsin	Wu	National Taiwan University	Taiwan
Di	Wu	Hefei University of Technology	China
Ernest	Wu	IBM	United States
Heng	Wu	IBM	United States
Huaqiang	Wu	Tsinghua University	China
Jiang	Wu	University of Electronic Science and Technology of China	China
Ke	Wu	Polytechnique Montreal	Canada
Peng	Wu	MIT	United States
Ping	Wu	Northwest Institute of Nuclear Technology	China
Shin-Tson	Wu	University of Central Florida	United States
Tian-Li	Wu	National Yang Ming Chiao Tung University	Taiwan
Wei	Wu	University of Southern California	United States
Wei-Jing	Wu	Institute of Polymer Optoelectronic Materials and Devices	China
Xiaohan	Wu	Fudan University	China
Yang	Wu	China Academy of Engineering Physics Institute of Applied Electronics	China
Yifeng	Wu	Transphorm Inc.	United States
Yuh-Renn	Wu	National Taiwan University	Taiwan
Yung-Chun	Wu	National Tsing Hua University	Taiwan
Yung-Hsien	Wu	National Tsing-Hua University	Taiwan
George	Xereas	McGill University	Canada
Yue	Xi	Tsinghua University School of Integrated Circuits	China
Yidong	Xia	Nanjing University	China
Zhanbo	Xia	Ohio State University	United States
Minghan	Xian	Micron Technology Inc.	United States
Yang	Xiang	IMEC	Belgium
Ming	Xiao	Virginia Polytechnic Institute and State University	United States
T. Patrick	Xiao	Sandia National Laboratory	United States
Wenwu	Xiao	Xiangtan University	China
Chao	Xie	Anhui University	China
Huikai	Xie	Beijing Institute of Technology	China
Jin	Xie	Zhejiang University	China
Sihan	Xie	Massachusetts Institute of Technology	United States
Wenfa	Xie	Jilin University	China
Feng	Xu	Tsinghua University	China
Guangwei	Xu	University of Science and Technology of China	China
Guangyu	Xu	University of Massachusetts Amherst	United States
Hongya	Xu	Lanzhou University	China
Nuo	Xu	University of California Berkeley	United States
Xiaobao	Xu	Nanjing University of Science and Technology	China
Xiaopeng	Xu	Synopsys Inc.	United States
Xiaoxin	Xu	Institute of Microelectronics of Chinese Academy of Sciences	China
Yang	Xu	Zhejiang University	China
Yuehang	Xu	University of Electronic Science and Technology of China	China
Jin	Xue	Massachusetts Institute of Technology	United States

First Name	Last Name	Affiliation	Country
Kan-Hao	Xue	Huazhong University of Science and Technology	China
Xiaoyong	Xue	Fudan University	China
Chandan	Yadav	National Institute of Technology Calicut	India
Manoj	Yadav	POSTECH MSE	South Korea
Sachin	Yadav	IMEC	Belgium
Eilam	Yalon	Technion—Israel Institute of Technology	Israel
Yuusuke	Yamaguchi	University of Fukui	Japan
Keisuke	Yamamoto	Kyushu University	Japan
Xingbin	Yan	Male Doctoral Supervisor Lanzhou Institute of Chemical Physics	China
Yan	Yan	Shenzhen University	China
Yang	Yan	University of Electronic Science and Technology of China	China
Chia-Ming	Yang	Chang Gung University	Taiwan
Chih Chung	Yang	National Taiwan University	Taiwan
Huan	Yang	Peking University Shenzhen Graduate School	China
Joshua	Yang	Viterbo College	United States
Ling	Yang	Xidian University	China
Shu	Yang	Zhejiang University	China
Tsung-Han	Yang	Arizona State University	United States
Weiqing	Yang	Southwest Jiaotong University	China
Xiangyu	Yang	Micron Technology Inc.	United States
Yang	Yang	University of Technology Sydney	Australia
Yansong	Yang	The Hong Kong University of Science and Technology	Hong Kong
Yuchao	Yang	Peking University	China
Peng	Yao	Tsinghua University Institute of Microelectronics	China
Yao	Yao	Chengdu University of Information Technology	China
Yixu	Yao	Chinese Academy of Sciences	China
Elahe	Yarmoghaddam	New York University Tandon School of Engineering	United States
Jiandong	Ye	Nanjing University	China
Peide	Ye	Purdue University	United States
Zhou	Ye	Shenzhen University	China
Ping-Hung	Yeh	Tamkang University	Taiwan
Teng-Hao	Yeh	Macronix International Company, Ltd.	Taiwan
Wei-Chang	Yeh	National Tsing Hua University	Taiwan
Bo	Yi	University of Electronic Science and Technology of China	China
Yong	Yin	University of Electronic Science and Technology of China	China
Hanbin	Ying	Georgia Institute of Technology	United States
Geonwook	Yoo	Soongsil University	South Korea
Hocheon	Yoo	Gachon University	South Korea
Sungmin	Yoon	Kyung Hee University	South Korea
Youngki	Yoon	University of Waterloo	Canada
Long	You	Huazhong University of Science and Technology	China
Sheng-Joue	Young	National United University	United States
Hao	Yu	IMEC	Belgium
Hongbin	Yu	Arizona State University	United States
Hsin-Chieh	Yu	National Yang Ming Chiao Tung University	Taiwan
Hyun-Yong	Yu	Korea University	South Korea
Xiao	Yu	Zhejiang University	China
Yongqiang	Yu	Hefei University of Technology	China
Feng	Yun	Xi'an Jiaotong University	China
Sabahattin	Yurt	QUALCOMM Inc.	United States
Shaw	Zachary	Texas Tech University	United States
Nicolò	Zagni	University of Modena and Reggio Emilia	Italy

First Name	Last Name	Affiliation	Country
Houman	Zahedmanesh	IMEC	Belgium
Cristian	Zambelli	University of Ferrara	Italy
Zhigang	Zang	Chongqing University	China
Enrico	Zanoni	Università degli Studi di Padova	Italy
Tommaso	Zanotti	Università degli Studi di Modena e Reggio Emilia	Italy
Alexander	Zaslavsky	Brown University	United States
Valentina	Zega	Polytechnic University of Milan	Italy
Fei	Zeng	Tsinghua University	China
Ke	Zeng	University at Buffalo	United States
Lang	Zeng	Beihang University	China
Longhui	Zeng	University of California San Diego	United States
Yuping	Zeng	University of Delaware	United States
Carl-Mikael	Zetterling	KTH Royal Institute of Technology	Sweden
Yiqiang	Zhan	Fudan University	China
Chen	Zhang	IBM	United States
Dongzhi	Zhang	China University of Petroleum	China
Fujun	Zhang	Institute of Optoelectronic Technology	China
Han	Zhang	Shenzhen University	China
Huilong	Zhang	University of Wisconsin-Madison	United States
Jian	Zhang	Liverpool John Moores University	United Kingdom
Jiawei	Zhang	Shandong University	China
Jinfeng	Zhang	Xidian University	China
Jun	Zhang	National University of Defense Technology	China
Lei	Zhang	Institute of Materials Research and Engineering	Singapore
Liang	Zhang	University of Strathclyde	United Kingdom
Lining	Zhang	Peking University	China
Lining	Zhang	Shenzhen University	China
Long	Zhang	Southeast University	China
Meng	Zhang	College of Electronic Science and Technology	China
Min	Zhang	Peking University Shenzhen Graduate School	China
Qi	Zhang	Huazhong University of Science and Technology	China
Qichun	Zhang	City University of Hong Kong	Hong Kong
Rui	Zhang	Zhejiang University	China
Ruifeng	Zhang	University of Electronic Science and Technology of China	China
Shengdong	Zhang	Peking University	China
Shuye	Zhang	Harbin Institute of Technology	United States
Wei	Zhang	Liverpool John Moores University	United Kingdom
Wentong	Zhang	University of Electronic Science and Technology of China	China
Xiaodong	Zhang	Suzhou Institute of Nano-Tech & Nano-Bionics, CAS	China
Xuchen	Zhang	Georgia Institute of Technology	United States
Yachao	Zhang	Xidian University	China
Yide	Zhang	California Institute of Technology	United States
Yong	Zhang	University of Electronic Science and Technology of China	China
Yue	Zhang	Beihang University	China
Yuhao	Zhang	Virginia Tech	United States
Bo	Zhao	Stanford University	United States
Chun	Zhao	Xi'an Jiaotong-Liverpool University	China
Dewei	Zhao	Sichuan University	China
Feng	Zhao	Washington State University	United States
Liang	Zhao	Zhejiang University	China
Ming	Zhao	IMEC	Belgium
Qing-Tai	Zhao	Forschungszentrum Julich GmbH	Germany
Weisheng	Zhao	Beihang University	China

First Name	Last Name	Affiliation	Country
Xiaojin	Zhao	Shenzhen University	China
You	Zhao	Xi'an Jiaotong University	China
Yuda	Zhao	Zhejiang University	China
Huai	Zheng	Wuhan University	China
Jun	Zheng	Institute of Semiconductors Chinese Academy of Sciences	China
Qiwen	Zheng	Chinese Academy of Sciences	China
Xiao-Hong	Zheng	Institute of Solid State Physics Chinese Academy of Sciences	China
Xuejun	Zheng	Xiangtan University	China
Zheyang	Zheng	Hong Kong University of Science and Technology	Hong Kong
Haizheng	Zhong	Beijing Institute of Technology	China
Sihua	Zhong	Jiangsu Ocean University	China
Changjian	Zhou	South China University of Technology	China
Fan	Zhou	Apple Inc.	United States
Hang	Zhou	Peking University	China
Hong	Zhou	Xidian University	China
Peng	Zhou	Fudan University	China
Qi	Zhou	University of Electronic Science and Technology of China	China
Qifa	Zhou	University of Southern California	United States
Wei	Zhou	Hong Kong University of Science and Technology	Hong Kong
Xianda	Zhou	Sun Yat-sen University	China
Ye	Zhou	Shenzhen University	China
Fu Rong	Zhu	Hong Kong Baptist University	Hong Kong
Hui	Zhu	Beijing University of Technology	China
Huilong	Zhu	Institute of Microelectronics of Chinese Academy of Sciences	China
Jiadi	Zhu	Massachusetts Institute of Technology	United States
Jiejie	Zhu	Xidian University	China
Li Qiang	Zhu	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Min	Zhu	Shanghai Institute of Micro-System and Information Technology	China
Mingda	Zhu	Finisar Corporation	United States
Yao	Zhu	Institute of Microelectronics, Agency for Science, Technology and Research	Singapore
Fei	Zhuge	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Fuwei	Zhuge	Huazhong University of Science and Technology	China
Serge	Zhuiykov	Ghent University	Belgium
Cheng	Zhuo	Zhejiang University	China
Martin	Ziegler	Technische Universitat Ilmenau	Germany
Thomas	Zimmer	Université de Bordeaux	France
Lars	Zimmermann	IHP Microelectronics	Germany
Cezar	Zota	IBM	Switzerland
Xinbo	Zou	ShanghaiTech University	China
Ahmad	Zubair	Intel Corporation	United States